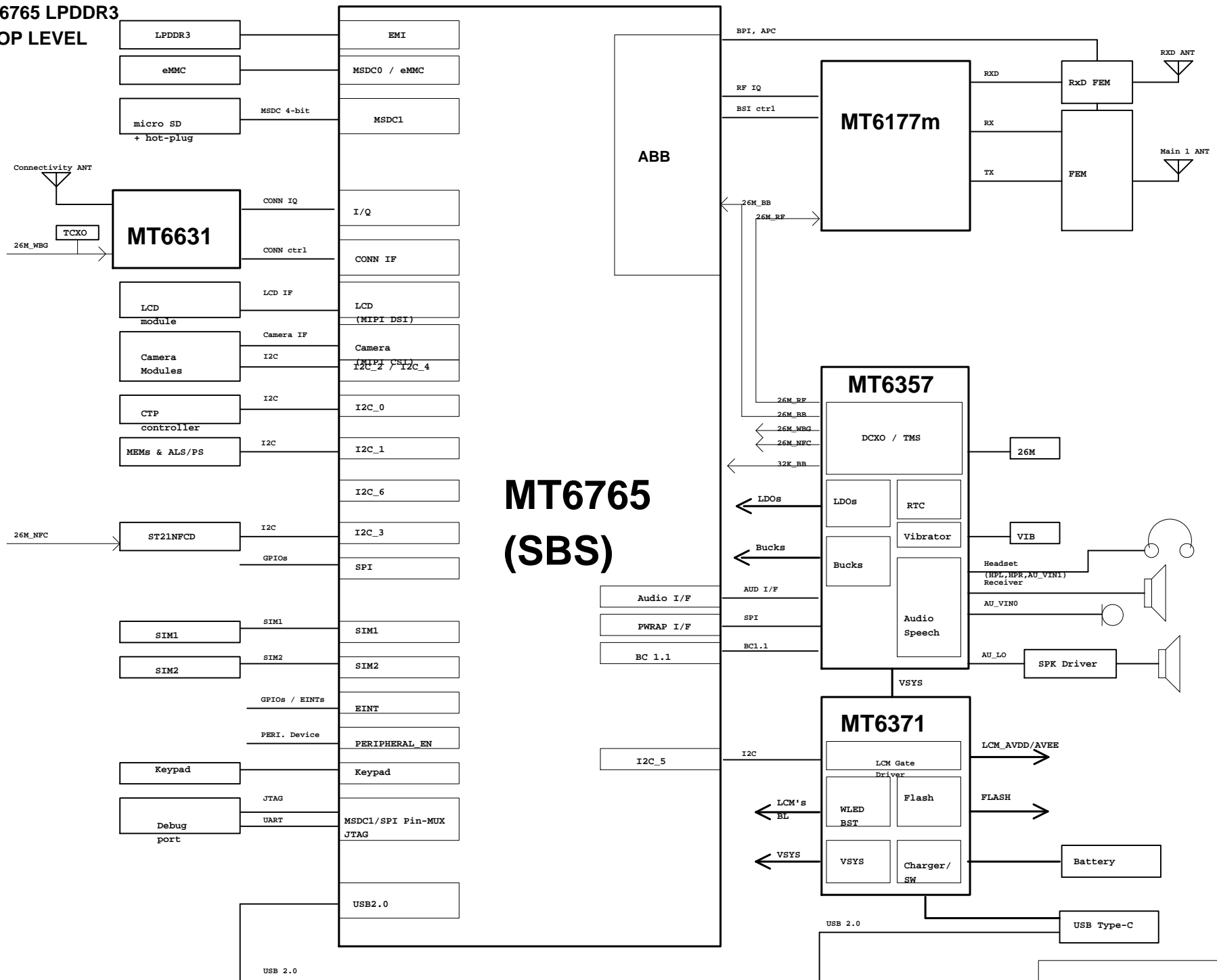


Project : MT6765 LPDDR3

REF_SCH TOP LEVEL

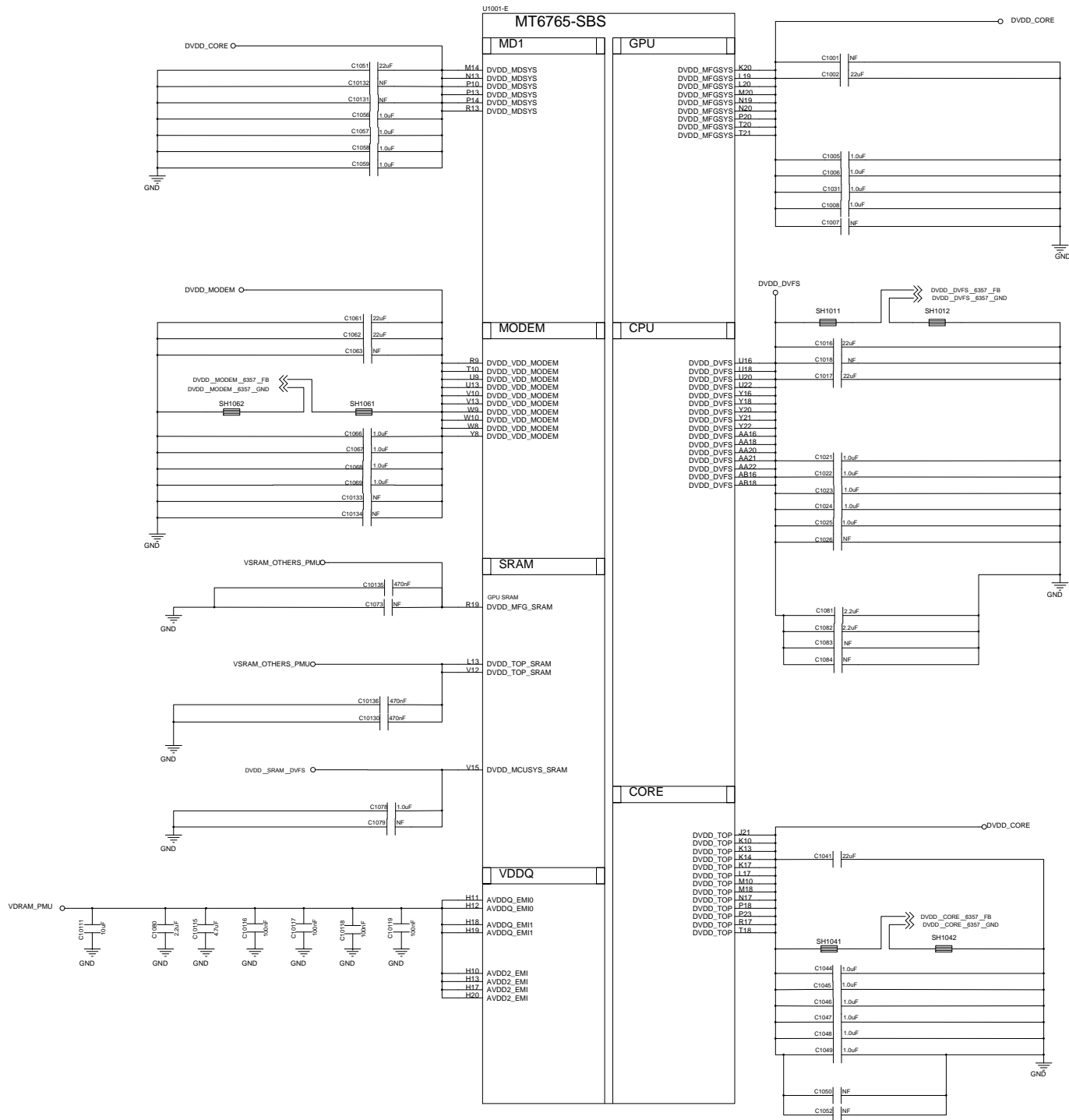


MT6765 (SBS)

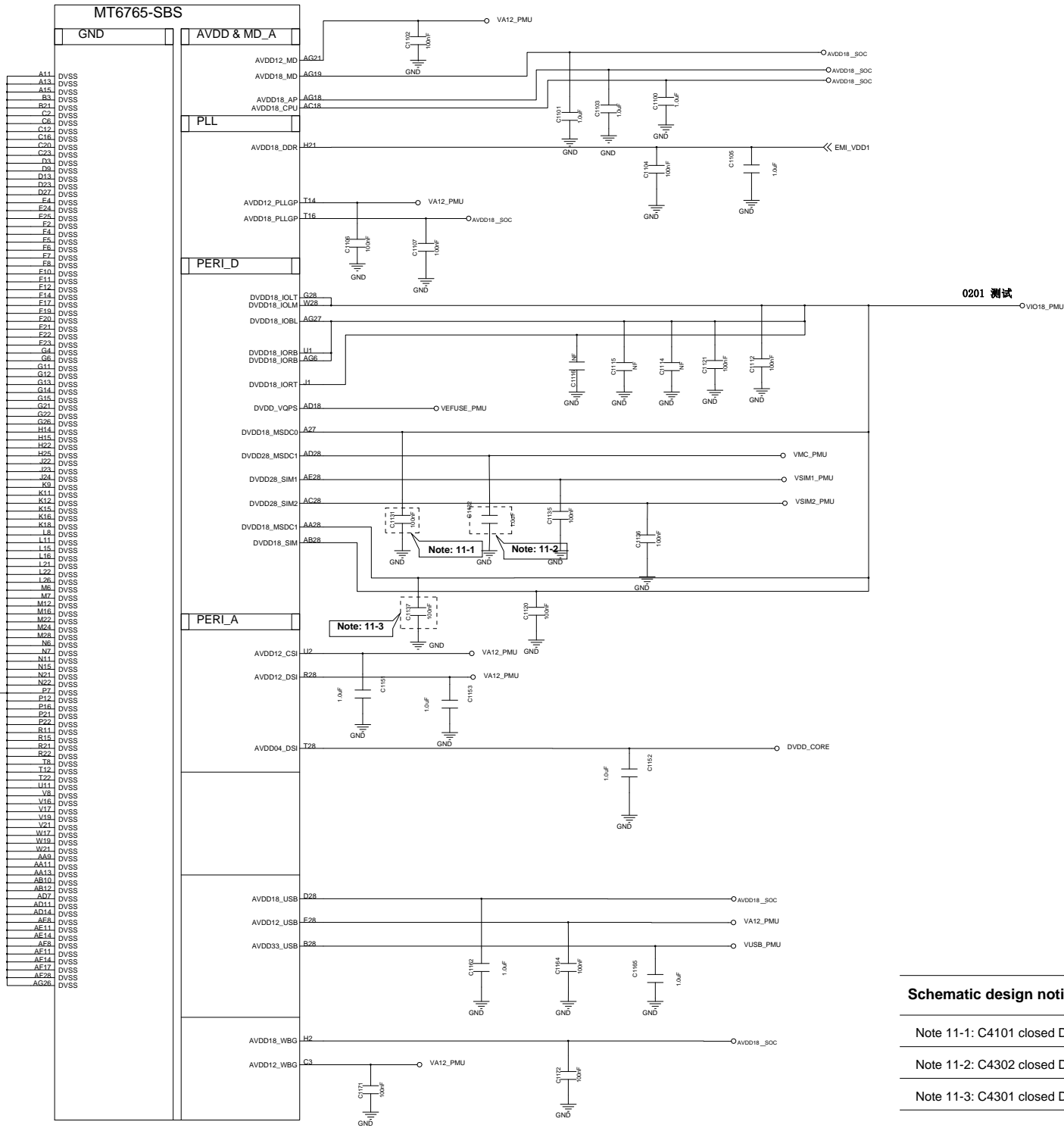
I2C	Sub SYS	Function	Part Number	I2C Spec.		i2C Slave Address / Write / Read (7-bit mode)	
I2C-0	AP	Cap Touch controller	GT1151	400 Kbps		0x5D	Write:0xBA / Read:0xBB
I2C-1 (I3C)	AP Sensor Hub	Magnetic Sensor	AK09918C	400 Kbps		0x0C	Write:0x18 / Read:0x19
		Ambient Light Sensor	CM36558	400 Kbps		0x51	Write:0xA2 / Read:0xA3
		Proximity Sensor					
		Pressure Sensor	BMP280	400 Kbps		0x77	Write:0xEE / Read:0xEF
I2C-2 (I3C)	AP	Rear Camera	IMX230	400 Kbps		0x1A	Write:0x34 / Read:0x35
			EEPROM	400 Kbps		0x50	Write:0xA0 / Read:0xA1
			AF driver	400 Kbps		0x0C	Write:0x18 / Read:0x19
I2C-3	AP	Audio Smart PA	RT5510	400 Kbps		0x34	Write:0x68 / Read:0x69
		NFC	ST21NFCD	400 Kbps		0x08	Write:0x10 / Read:0x11
I2C-4 (I3C)	AP	Front Camera	S5K2T7	400 Kbps		0x2D	Write:0x5A / Read:0x5B
			EEPROM	400 Kbps		0x52	Write:0xA4 / Read:0xA5
			AF driver=NA				
I2C-5	AP	Sub-PMIC	MT6371 PMU	3.4 Mbps		0x34	Write:0x68 / Read:0x69
			MT6371 PD	3.4 Mbps		0x4E	Write:0x9C / Read:0x9D
I2C-6	AP						

Note : I2C Spec. : Standard mode (100 kbps) and Fast mode (400 kbps), Fast mode Plus (1 Mbps) and High-speed mode (3.4 Mbps)

Date	Category	Item
2017.11.24 (V0.1)	Page 05	V0.1 Release
2017.12.7 (V0.2)	Page 11	Change power of AVDD18_DDR(H21) from VIO18_PMU to EMI_VDD1, connecting EMI_VDD1 to SH2102 in star connection
	Page 12	Add Note 12-5
	Page 21	Add SH2102 for star connection among EMI_VDD1, AVDD18_SOC, and VIO18_PMU
	Page 22	
	Page 44	<ol style="list-style-type: none"> 1. Change C2304 from C / 1 / uF / 10V to C / 1 / uF / 6.3V 2. Change R2301 from R / 1.5 / K to R / 7.5 / K 3. Update eLDD3 power off sequence, change C4422 from 0.1uF to 2.2uF, and change C4423 from 0.1uF to 1uF
	Page 51	<ol style="list-style-type: none"> 2. Change VDD1 power of eMCP from VIO18_PMU to EMI_VDD1, fulfilling power rail in star connection 1. Add 2nd source plan for U5004 2. Add Note 51-3 and Note 51-4



MT6765-SBS



0201 测试

Note: 11-1

Note: 11-2

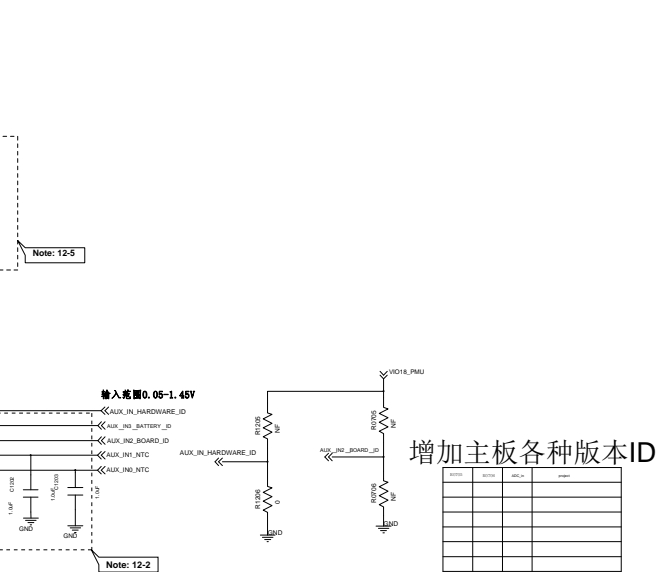
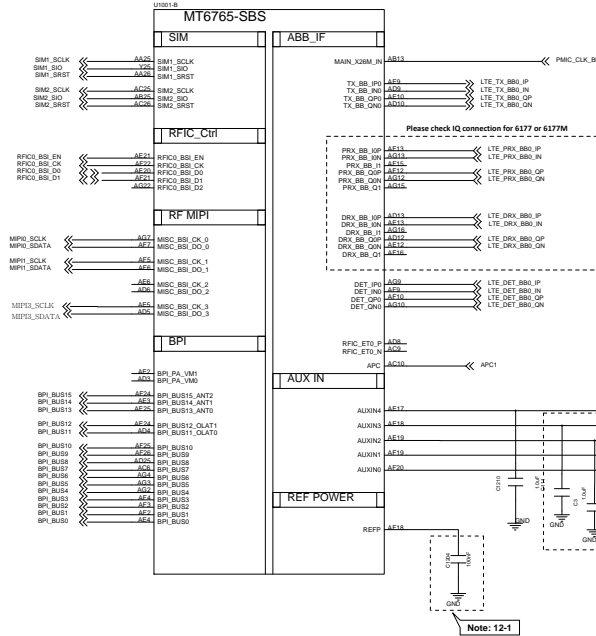
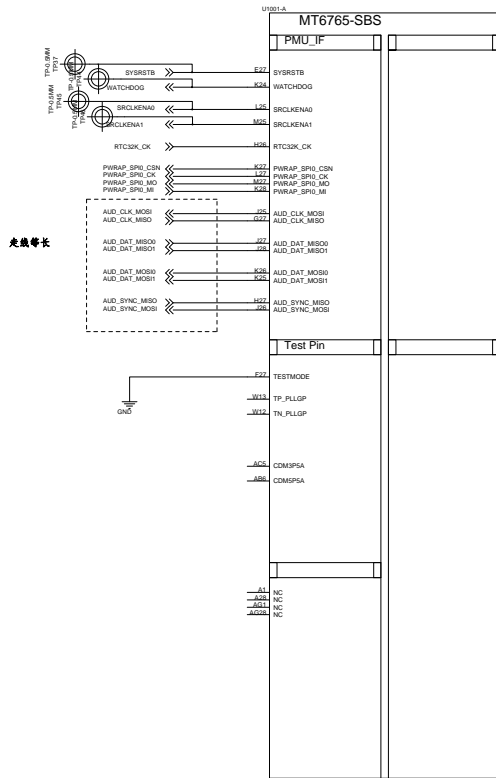
Note: 11-3

Schematic design notice of "11_BB_POWER_IO" page.

Note 11-1: C4101 closed DVDD18_MSDC0 150mil

Note 11-2: C4302 closed DVDD28_MSDC1 150mil

Note 11-3: C4301 closed DVDD18_MSDC1 150mil



Schematic design notice of "12_BB_1" page.

Note 12-1: The de-coupling cap. for REFP (AF18 ball) have to be placed as close to BB as possible.

Note 12-2: To shunt a 1uF capacitor in the AUXIN ADC input to prevent noise coupling. It should be placed as close to BB as possible. Connect the unused AUX ADC input to GND.

Note 12-3: *PWRAP_SPIO_CSN* and *AUD_DAT_MOSI0* are bootstrap pin to select which interface will be the JTAG pin out.

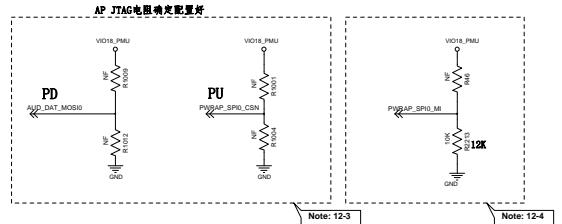
PWRAP_SPIO_CSN	AUD_DAT_MOSI0	JTAG Function	
default=PU	default=PD	AP_JTAG	MD_JTAG
HI	LO	N/A	N/A
HI	HI (by ext. PU)	SPI0+EINT8	SPI1+SPI3
LO (by ext. PD)	LO	SPI0+EINT8	N/A
LO (by ext. PD)	HI (by ext. PU)	MSDC1	N/A

Note 12-4: PWRAP_SPIO_MO and PWRAP_SPIO_MI are DDR type feature in bootstrap

PWRAP_SPIO_MI	Bootling interface
default=PU	DDR
LO (by ext. PD)	MSDC0 pin mux
LO (by ext. PD)	LPDDR3 follow LP3 Ref SCH.
HI	LPDDR4X follow LP4X Ref SCH.

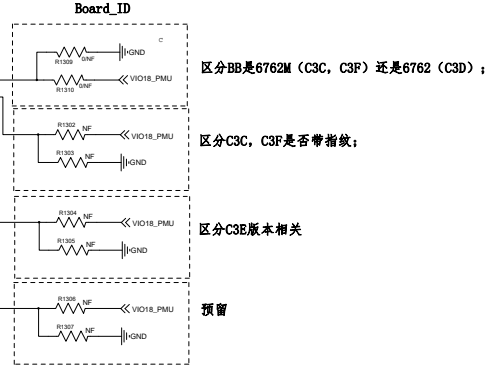
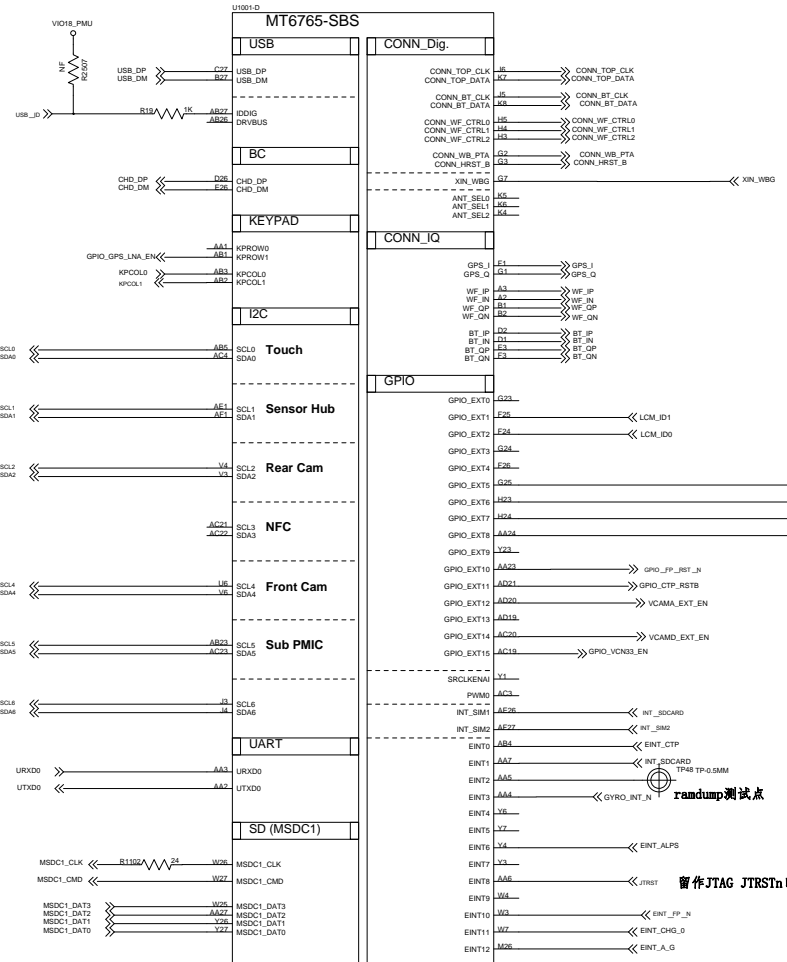
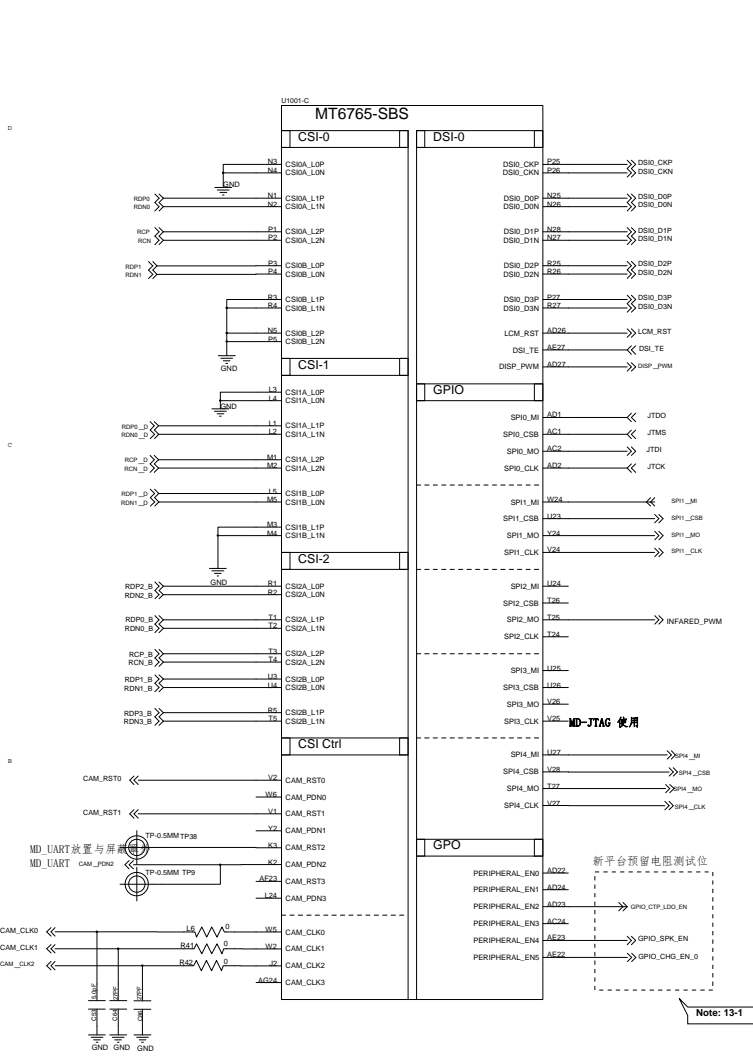
注释错误

Note 12-5: Please set unused IQ pins in NC



Note 12-3

Note 12-4



区分BB是6762M (C3C, C3F) 还是6762 (C3D) ;

区分C3C, C3F是否带指纹;

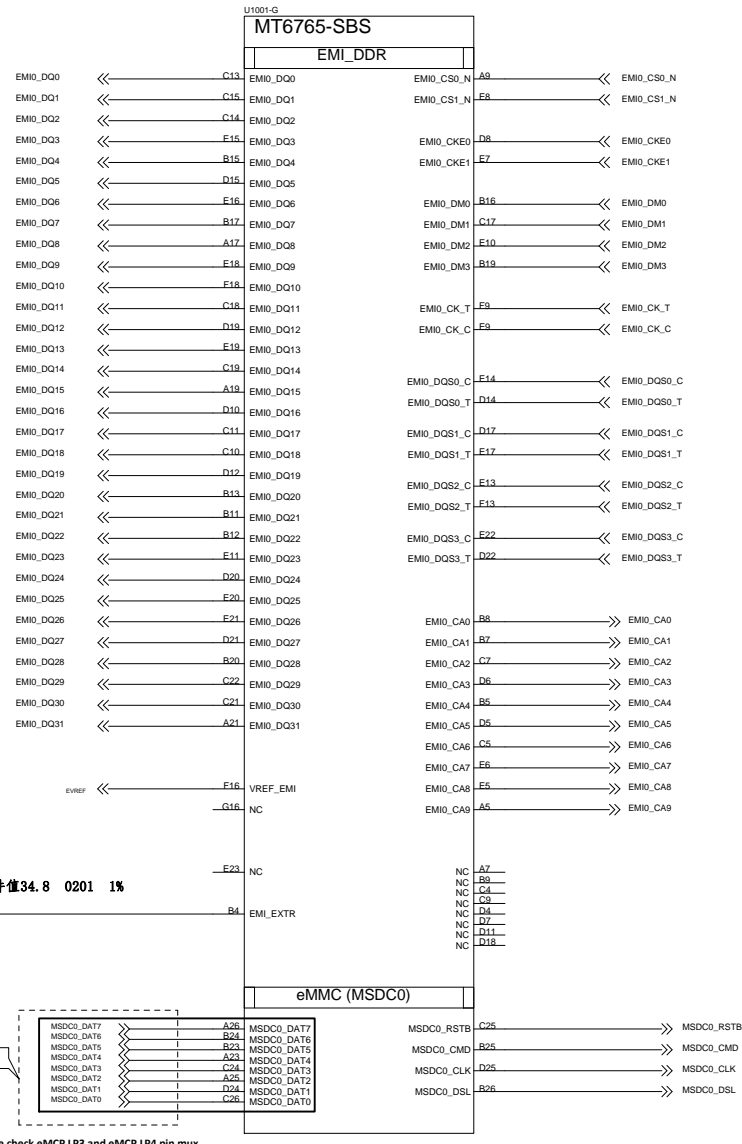
区分C3E版本相关

预留

Schematic design notice of "13_BB_2" page.

Note 13-1: The enable pin of acoustic or optoelectronic devices (e.g. SPK AMP/Backlight/Charger OCP/OVP) suggest to use Peripheral_EN[0:5]
If use other GPIOs as enable pin, suggest to reserve 0201 NC to GND

FIG	13_BB_2
REV	A1
MTK Confidential	
DATE	Thursday, November 09, 2017
SHEET	7 of 34



Note: 14-1 注意器件值34.8 0201 1%

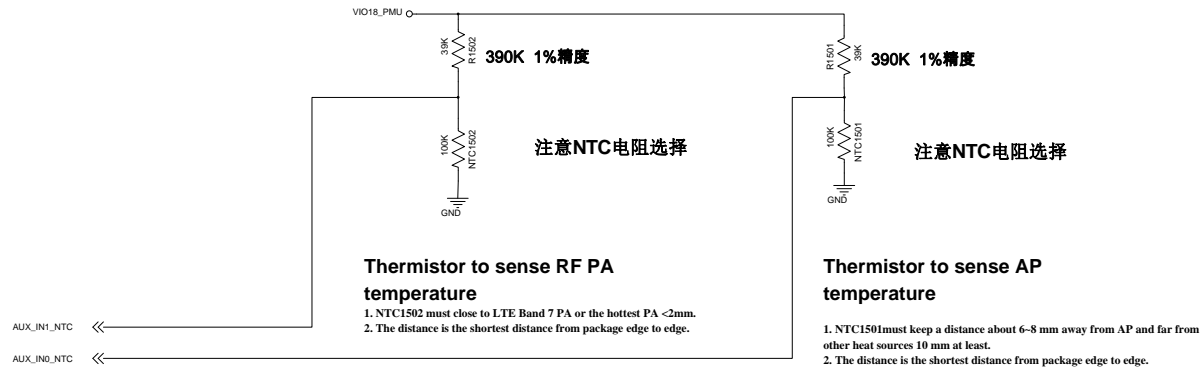
Note: 14-2

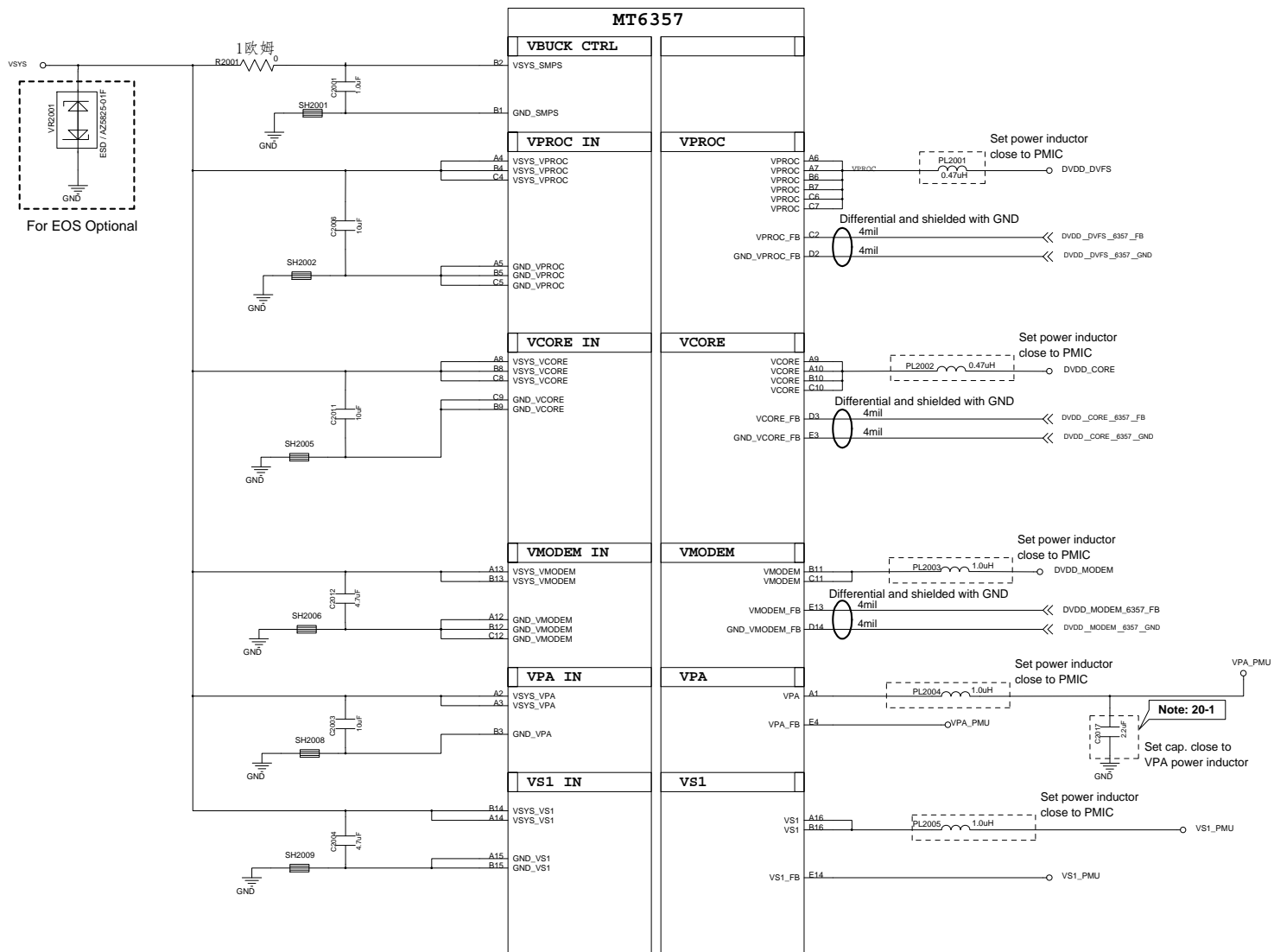
Please check eMCP LP3 and eMCP LP4 pin mux

Schematic design notice of "14_BB_3" page.

Note 14-1: R4001 please select 34.8 ohm (1%) resistor

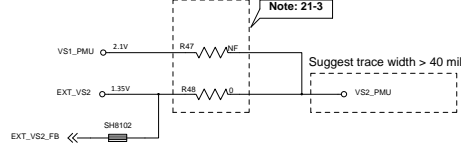
Note 14-2: Please check eMCP LP3 and eMCP LP4X pin mux



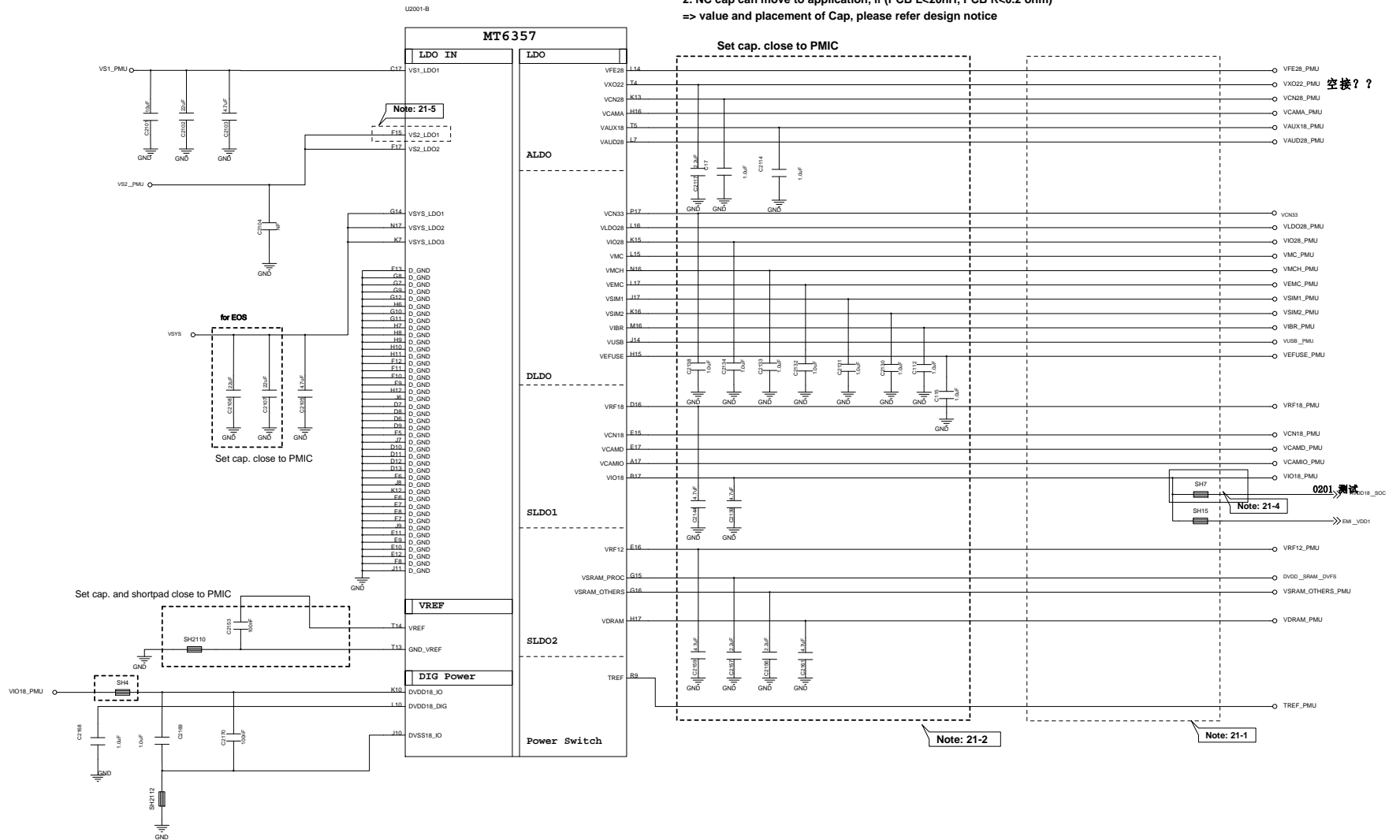


Schematic design notice of "20_POWER_MT6357_Buck"

Note 20-1: To reserve a cap., C2041, please choose 0603 size



1. "Typical Cap" defined in design notice is the minimum cap. to LDO Cout.
2. NC cap can move to application, if (PCB L<20nH, PCB R<0.2 ohm)
=> value and placement of Cap, please refer design notice



Schematic design notice of "21_POWER_MT6357_LDO"

Note 21-1: If these power trace can meet LDO layout constraint, these CAP can be NC or removed. Please refer to MT6357 design notice.

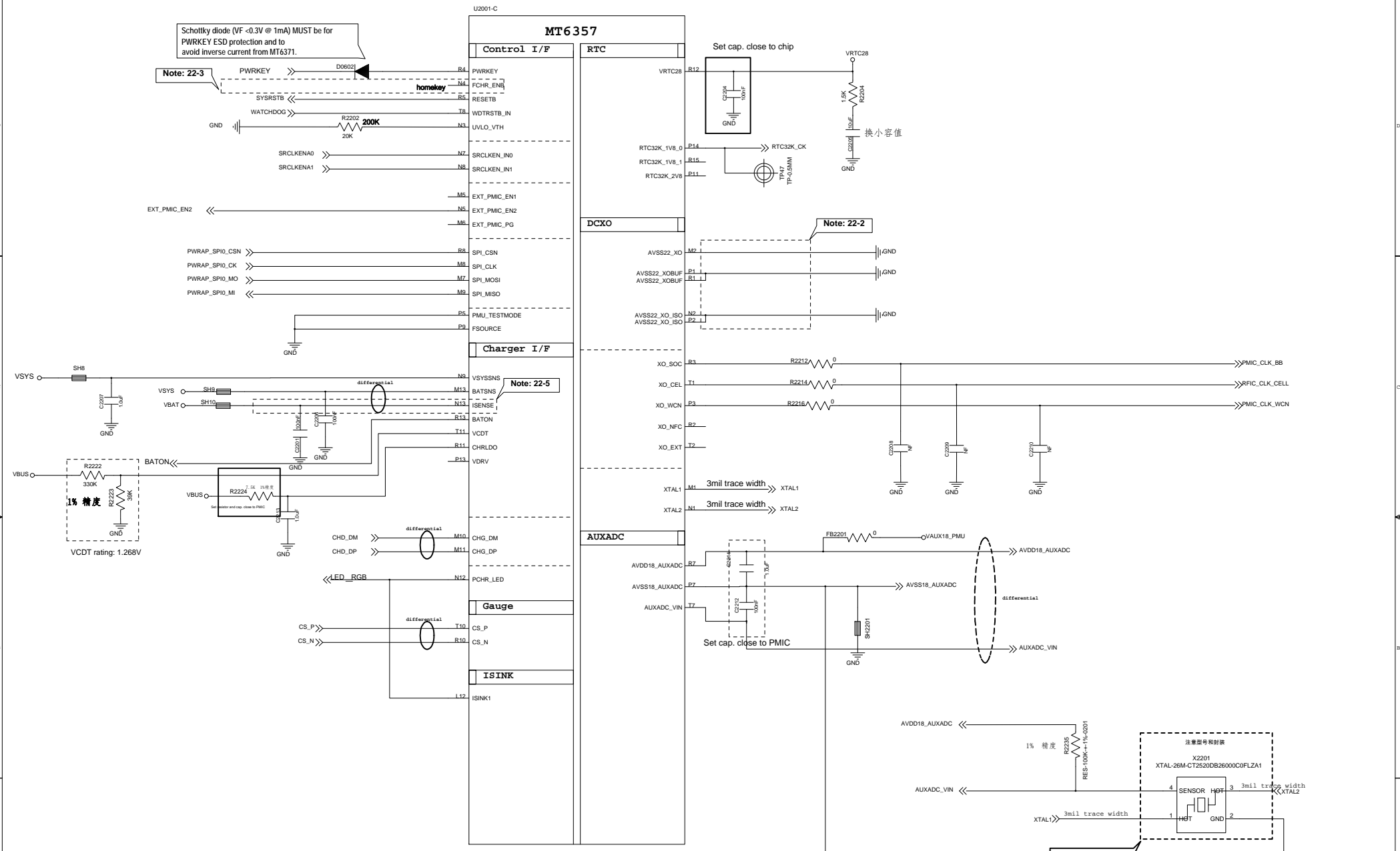
Note 21-2: Output cap range please follow MT6357CRV LDO design notice

Note 21-3: Ext Buck BOM option

	Ext. buck option	
	w/ EXT VS2 Buck	w/o EXT VS2 Buck
C2104	10uF	22uF
R2851	0-ohm, 0603	NC
R2852	NC	0-ohm, 0603

Note 21-4: Please set SH2101 close to C2141, making star connection between VIO18_PMU and AVDD18_SOC near to LDO cap. C2141
Please also refer to MT6357 design notice for further detail design information

Note 21-5: Please connect VS2_LDO1(F15) to VS1_PMU if voltage applied to VCAMD(E17) >= 1.3 V



Schematic design notice of "22_POWER_MT6357-IF"

Note 22-1: Please implement 2520 & 2016 Size TMS PCB co-layout. Please refer to MT6765_MT6357 Co-Clock Design Notice for co-layout guide

Note 22-2: 1. Please Connect P1 and R1 ball first and then to GND
 2. Please Connect P2 and N2 ball first and then to GND
 3. Please connect DCXO GND to main GND by independent L1-2 GND via.; DO NOT connect it through L1 GND

Note 22-3: Let floating if disable HOMEKEY function

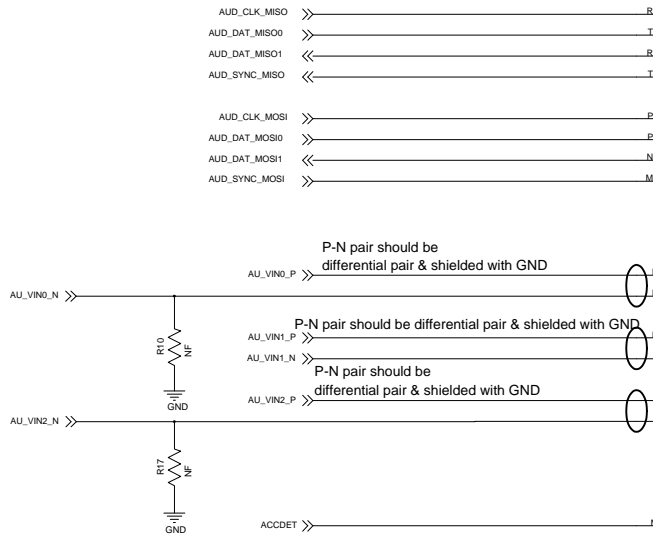
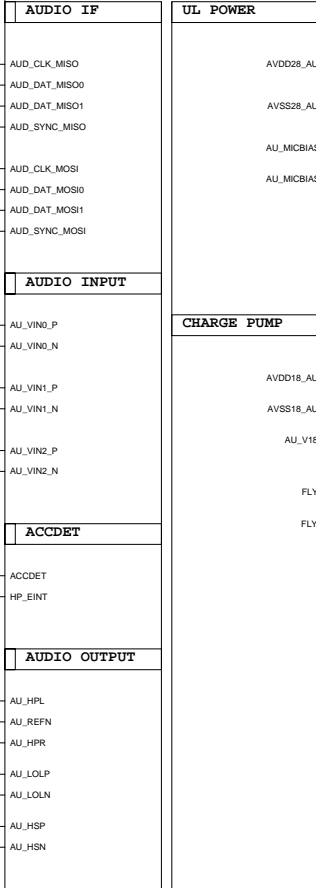
Note 22-4: Please follow MT6765_MT6357 Co-Clock Design Notice for Layout guide of VAUX18, then R8101 can use 0 ohm to replace BEAD.

Note 22-5: Please connect to battery connector

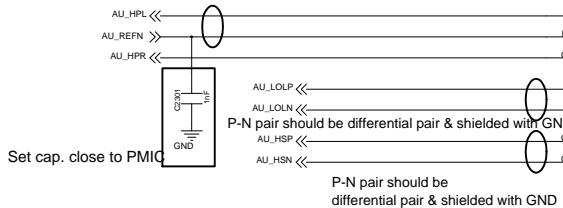
Route AVDD18_AUXADC, AUXADC_VIN, and AVSS18_AUXADC with 3mils width traces and well GND shielding

U2001-D

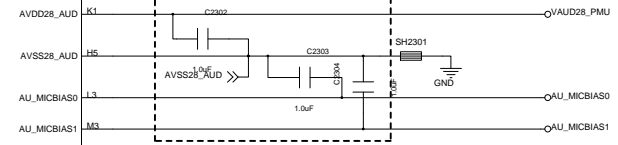
MT6357



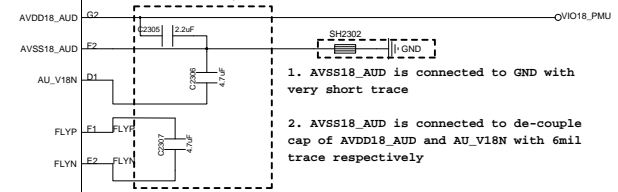
- AU_HPL and AU_HPR should be routed as single end signal, and be guarded by GND, up and down, left and right respectively
 - The suggested layout pattern of AU_HPL/ AU_HPR/ AU_REFN is " GND AU_HPL AU_REFN AU_HPR GND"



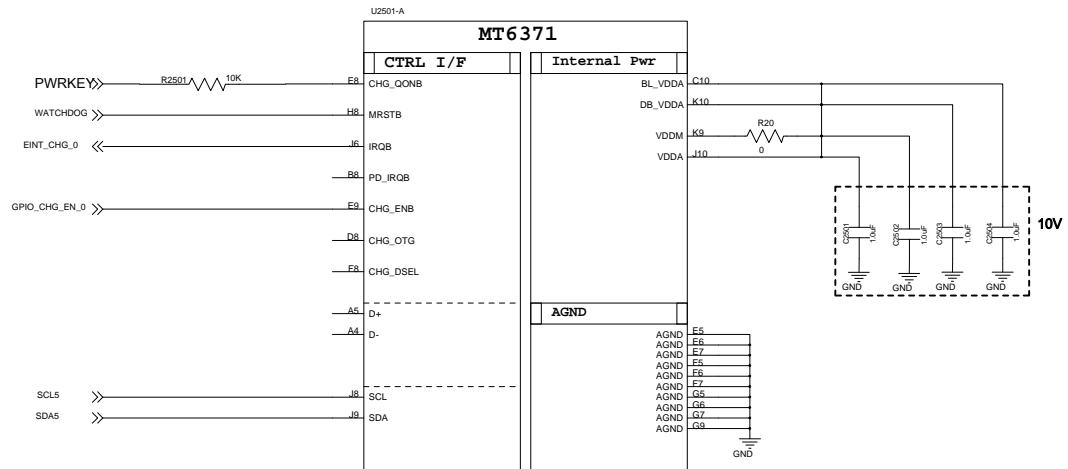
Set cap. and shortpad close to PMIC

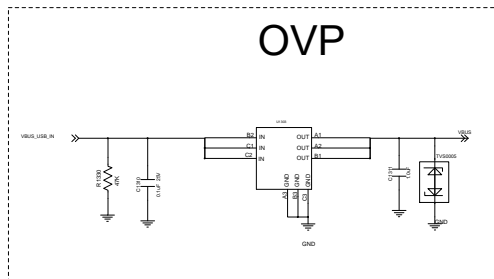
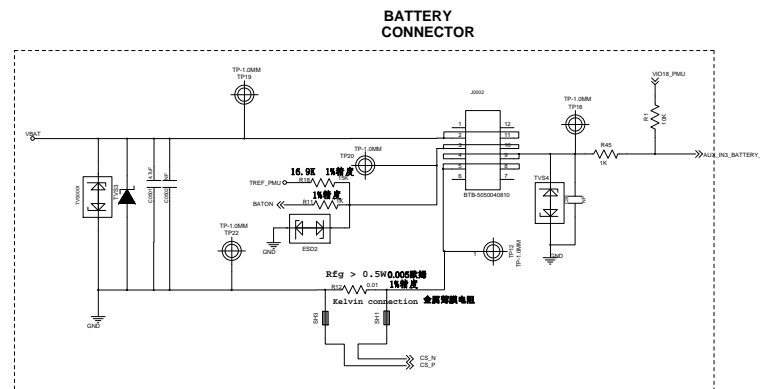
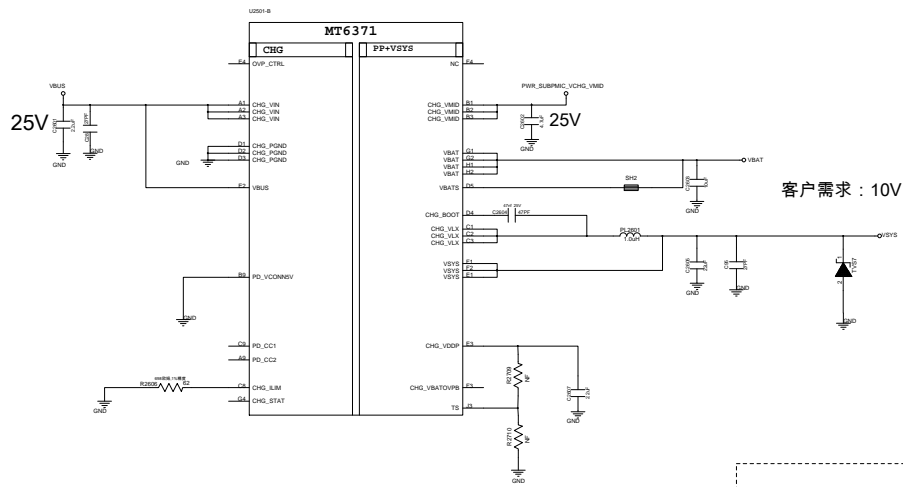


Set cap. close to PMIC



1. AVSS18_AUD is connected to GND with very short trace
2. AVSS18_AUD is connected to de-couple cap of AVDD18_AUD and AU_V18N with 6mil trace respectively

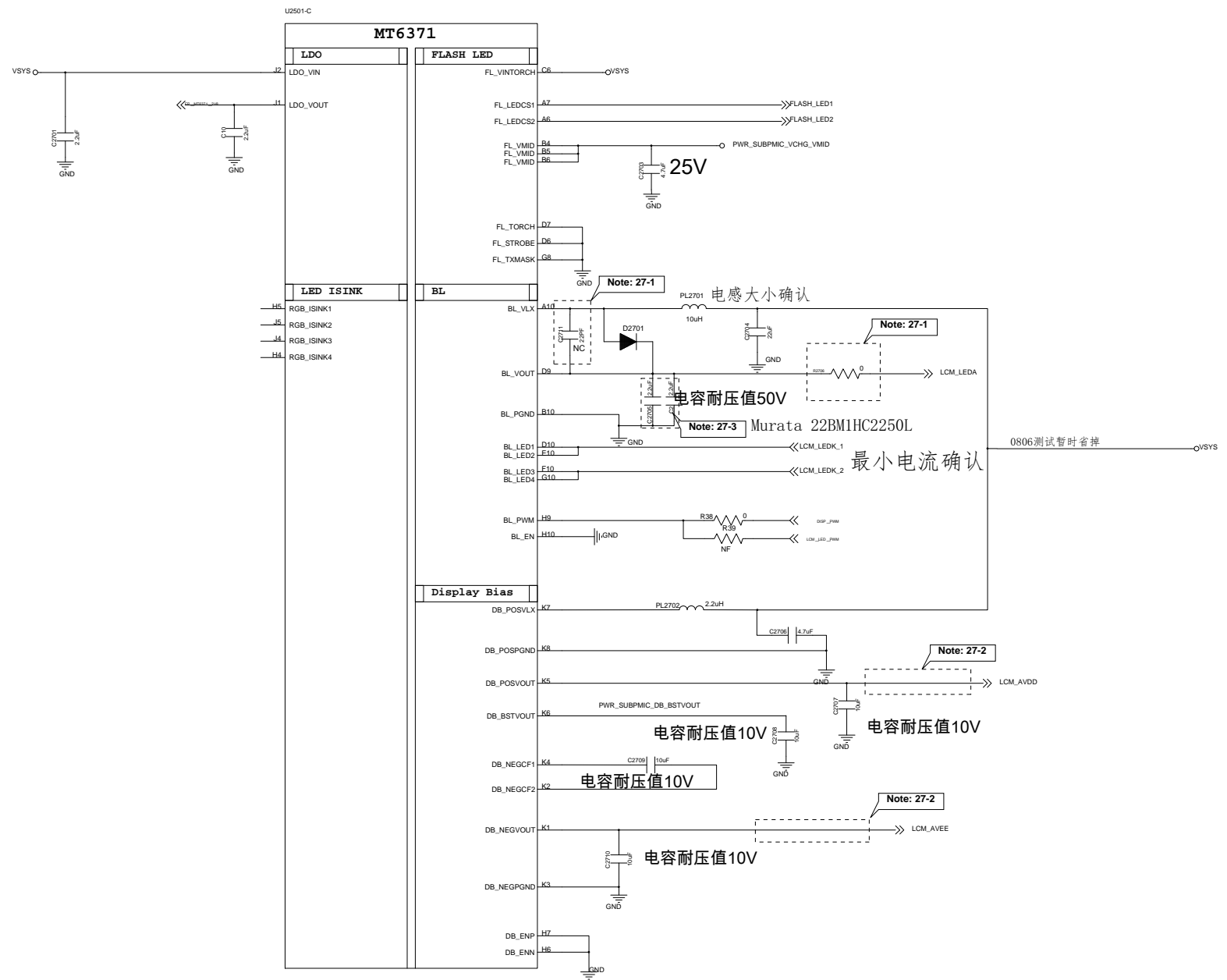




Schematic design notice of "26_POWER_MT6370-Charger + PP" page.

Note 26-1: For better ESD or surge performance we need choose suitable device for system protection. Please refer to [Surge device selection guide V2.0] provide by MTK.

Doc ID:	26_POWER_SubPMIC-Charger + PP
Rev:	MTK Confidential
File Path:	Hardware/Power/charger/26-power
Page No.:	18
Total Page:	24



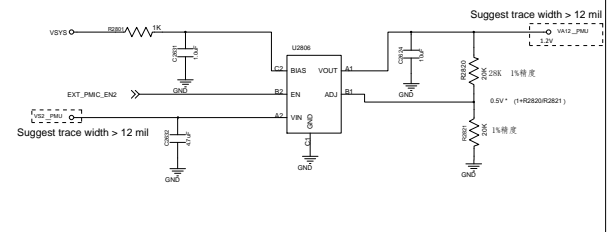
Schematic design notice of "27_POWER_SubPMIC-HV powers" page:

Note 27-1: To minimize RF de-sense, it is recommended to reserve 0-ohm and 0402 cap for BOM fine tuning.

Note 27-2: To minimize RF de-sense, it is recommended to reserve 0-ohm and 0201 cap. for BOM fine tuning.

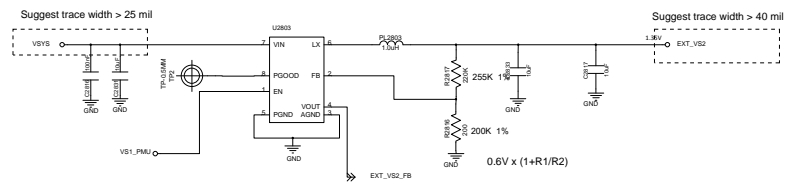
Note 27-3: C2705 could be replaced with $C / 1 / \mu F / 50V + C / 1 / \mu F / 50V$

LDO for VA12



Ext. Bulk for VS2

Note: 28-2



LDO for VCN33

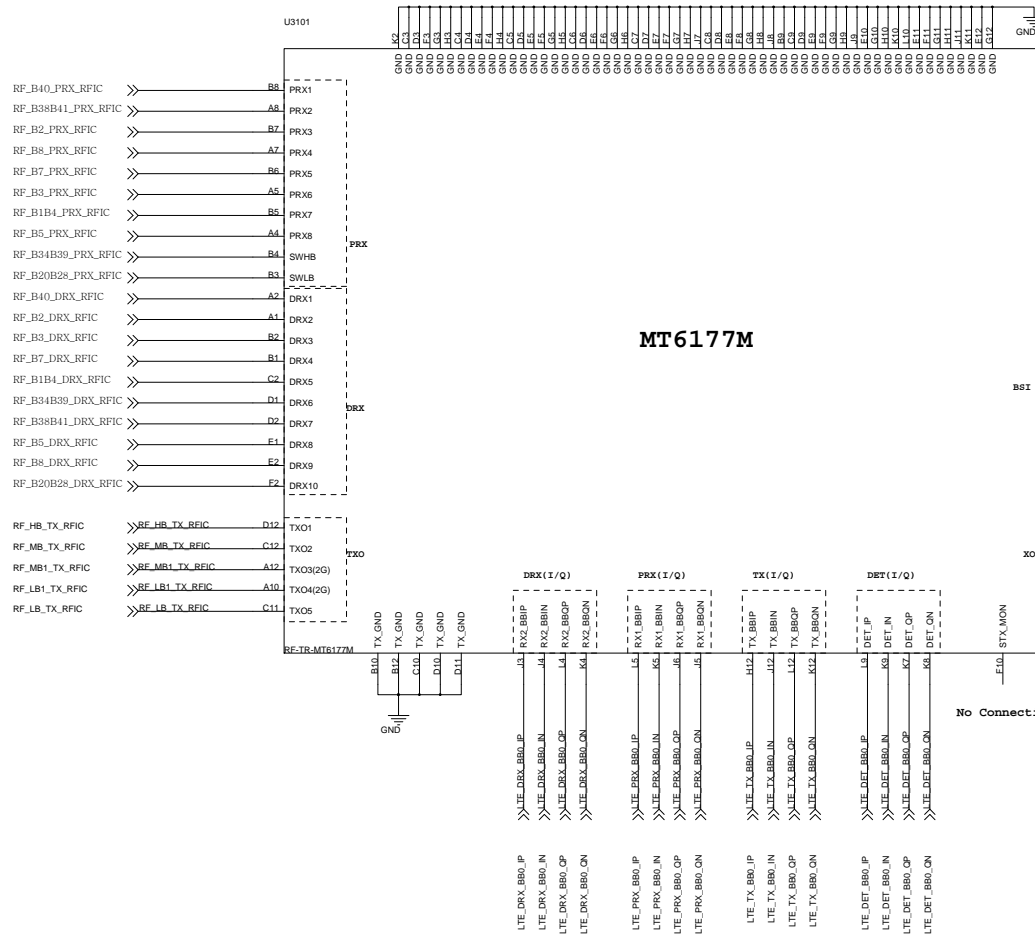
Please check MT67xx QVL

Schematic design notice of "28_POWER_ThirdParty-Power"

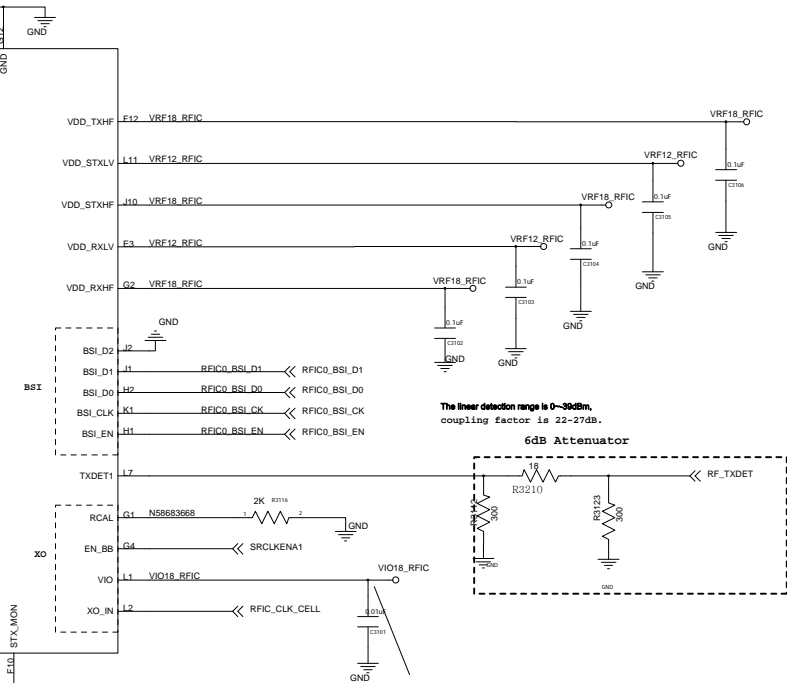
Note 28-1: VA12 Layout placement please close to AP

Note 28-2: VS2 Buck Layout placement please close to PMIC MT6357

Note 28-3: VCN33 LDO Layout placement please close to MT6631



MT6177M

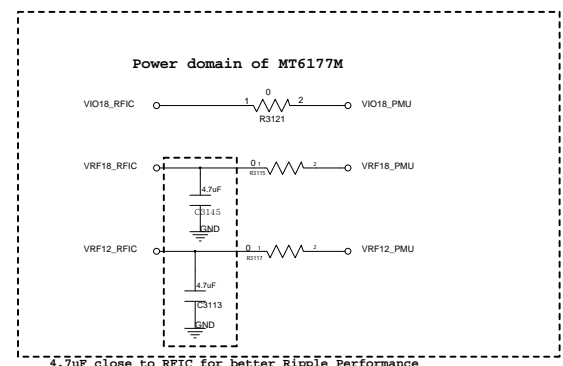


The linear detection range is 0-300db,
coupling factor is 22-27db.

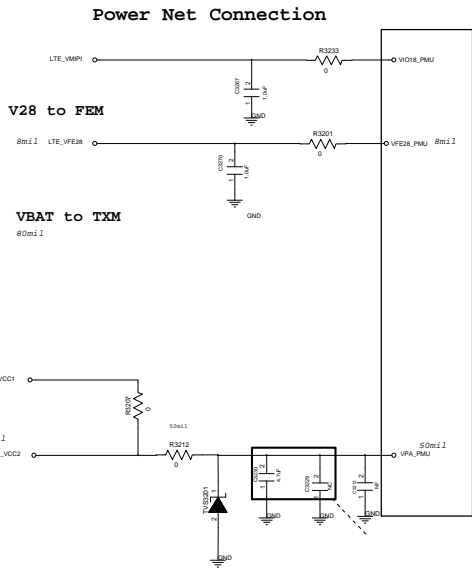
6dB Attenuator

For phone, remove 0R to avoid low slew rate.
For EVB, put test point.

No Connection, for PN test

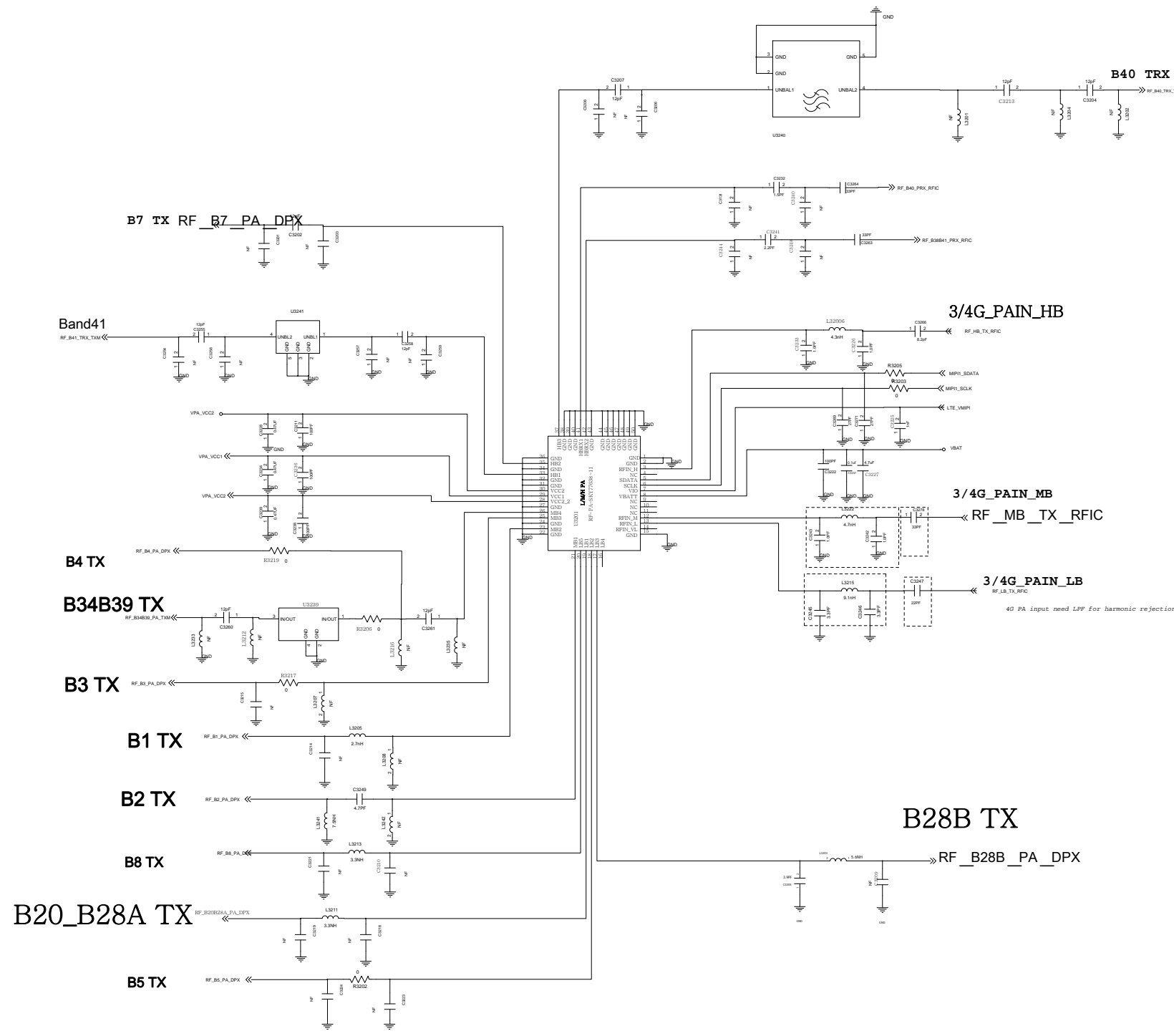


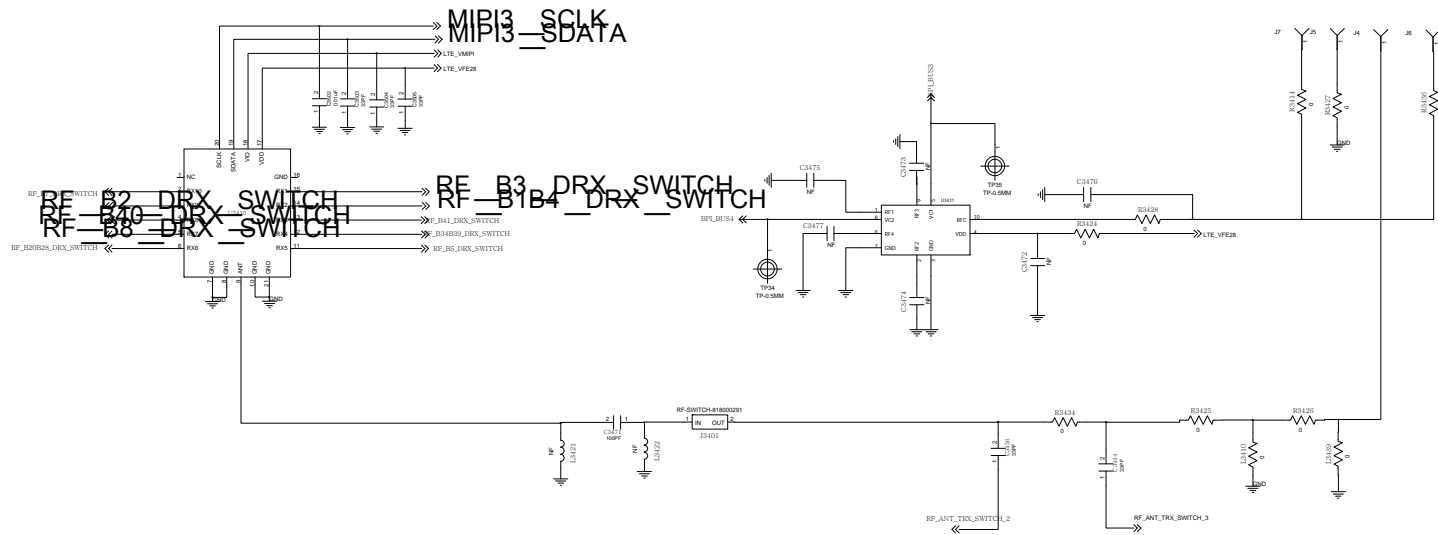
4.7uF close to RFIC for better Ripple Performance



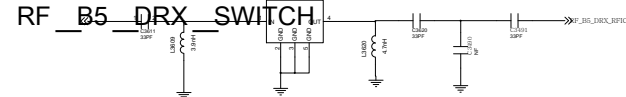
Note:
 Use 0603 for lower Capacitance drop

Note:
 Reserve at least one tuning cap. For PMIC
 VPA total cap requirement, the total cap at
 RF side should be in 6.2uF +/-5%
 10mi1

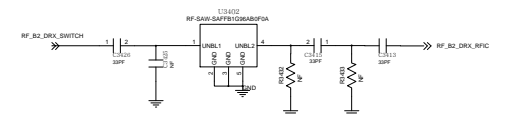




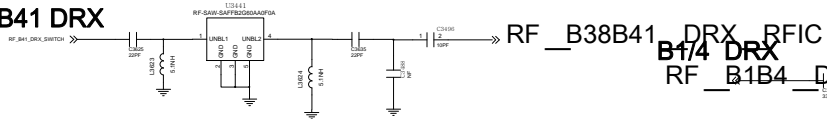
B5 DRX



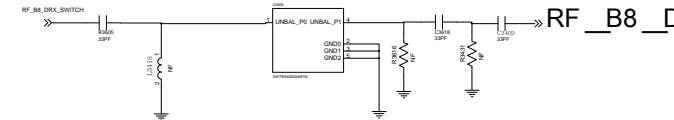
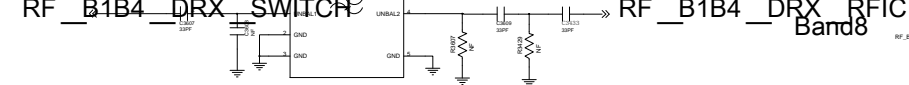
B2 DRX



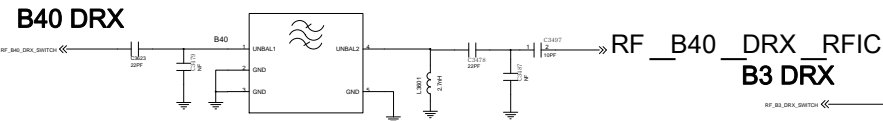
B38B41 DRX



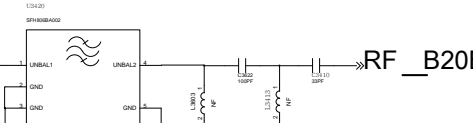
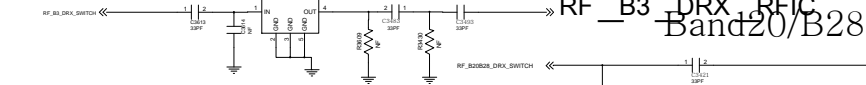
B14 DRX



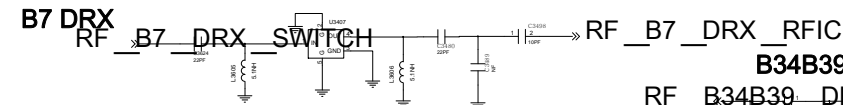
B40 DRX



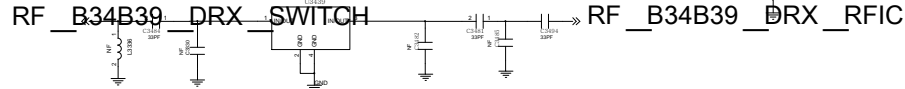
B3 DRX



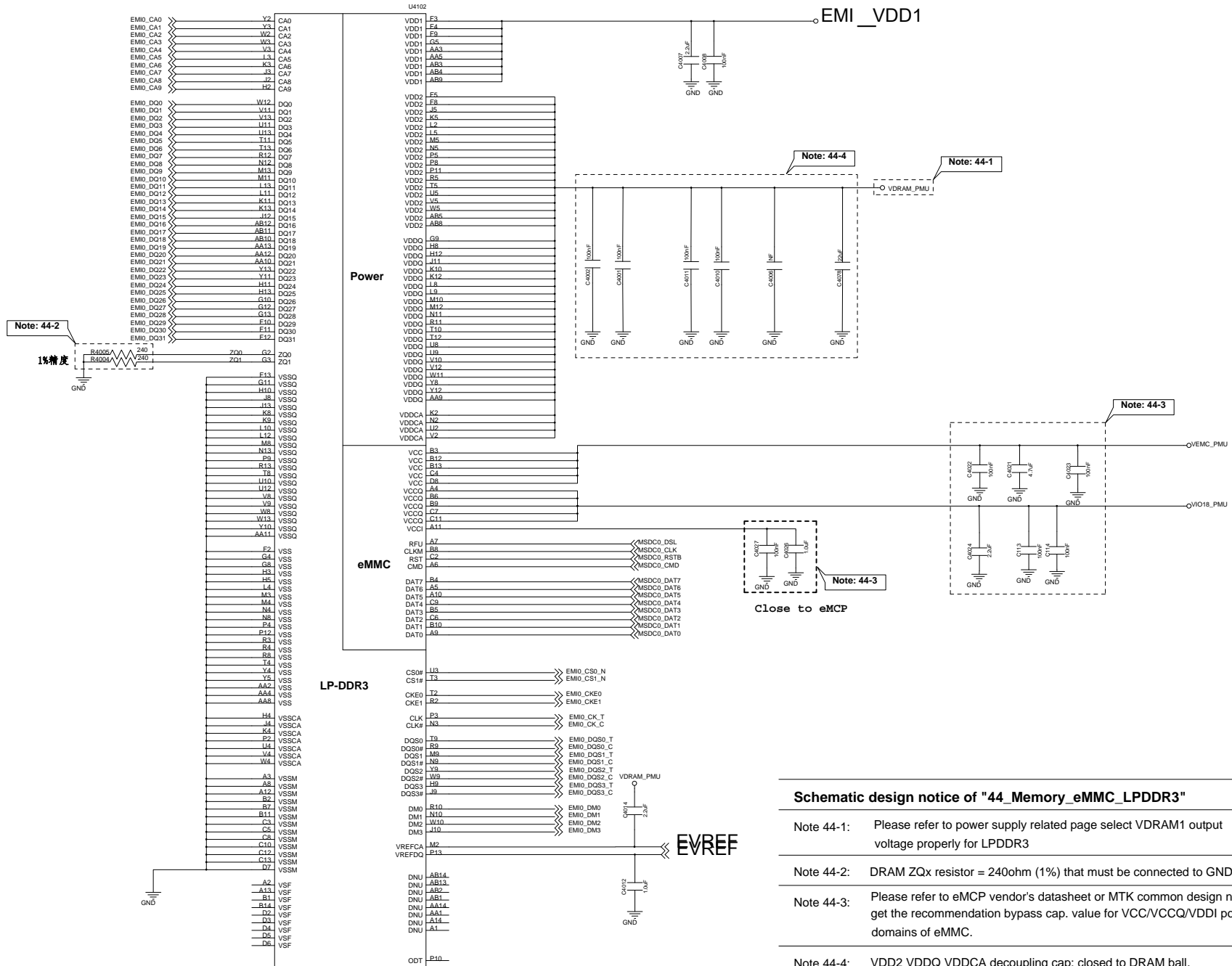
B7 DRX



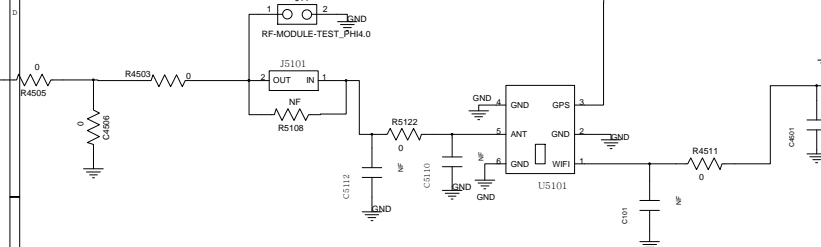
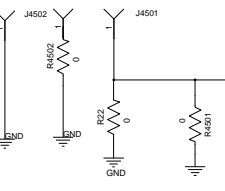
B34B39 DRX



eMMC+LPDDR3

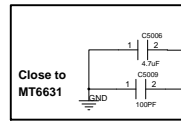
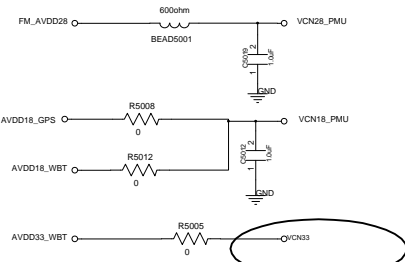
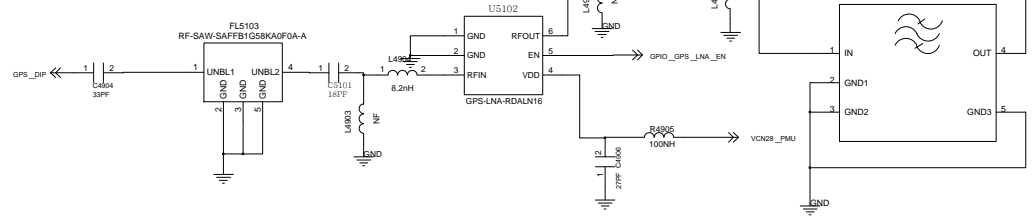


J4503

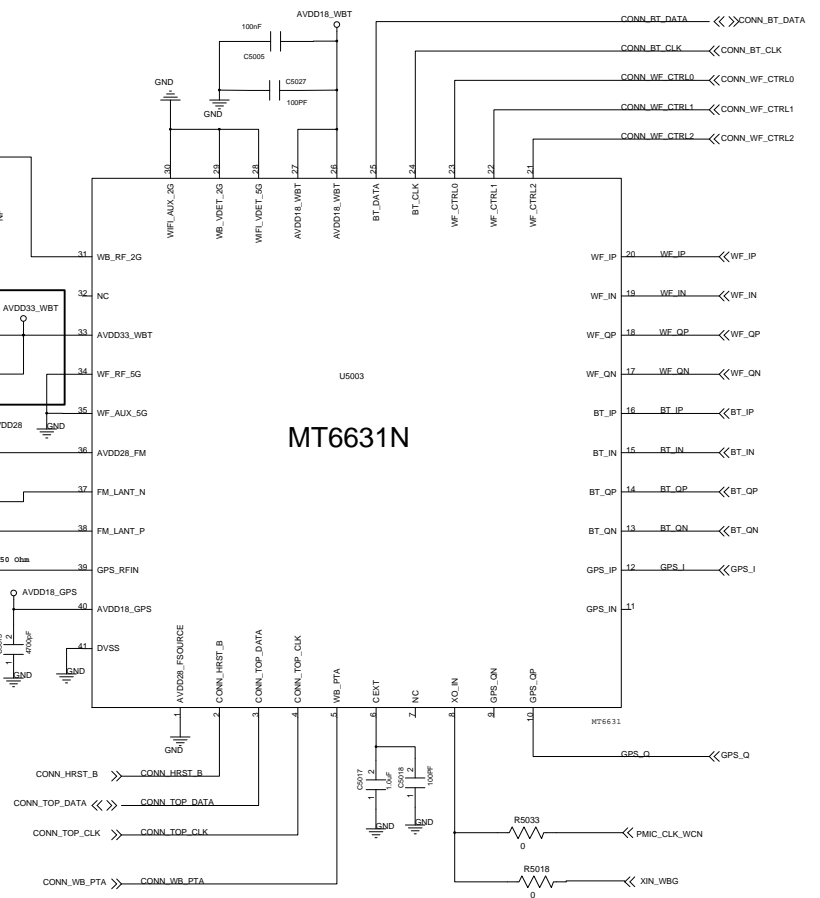


<Critical!!>
5G PCB loss is higher and trace must kept short and 50-ohm No layer transition

GPS xLNA
Close to ANT



MT6631N



PMIC R5016/R5017 NC, R5003/R5018 0ohm
TCXO R5016/R5017 0ohm, R5003/R5018 NC

File	51_CONNECTIVITY_CONSYS (A/Ddie)
Sub	A1
Date	Thursday, November 02, 2017
Sheet	23 of 34

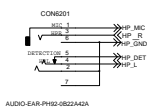
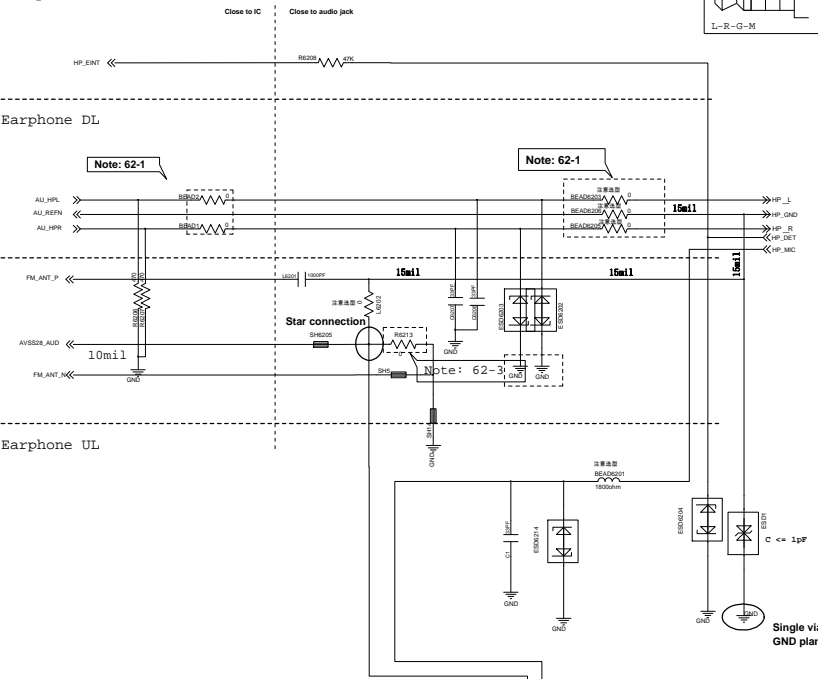
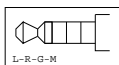
Earphone Audio

Earphone EINT

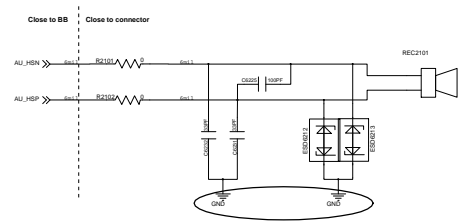
Earphone DL

Earphone UL

Earphone Microphone



Receiver



Connecting the GNDs together and then to main GND through single via

选择ACC MODE

Note: 62-4

Platform	WX353
Mode	ACC mode DCC mode
#207	HP_ENT HP_ENT2
Key-Deletion	ACCDET AU_VINB_P
R6229	1uF 0 ohm
R6230	1uF 0 ohm
R6209	1K IC
R6210	1.5K IC
R6219	IC 2.49K
R6231	4.7uF 0 ohm
R6225	0 ohm IC
R6208	47K ohm 47K ohm

Schematic design notice of "62_PERI_AUDIO_IO" page.

Note 62-1: Part # of BEAD6202, BEAD6203, BEAD6204 and BEAD6205 needs changed to "BLM188D102SN1" for high THD performance (-90dB) but this BOM change will results in FM RSSI 10dB degraded.

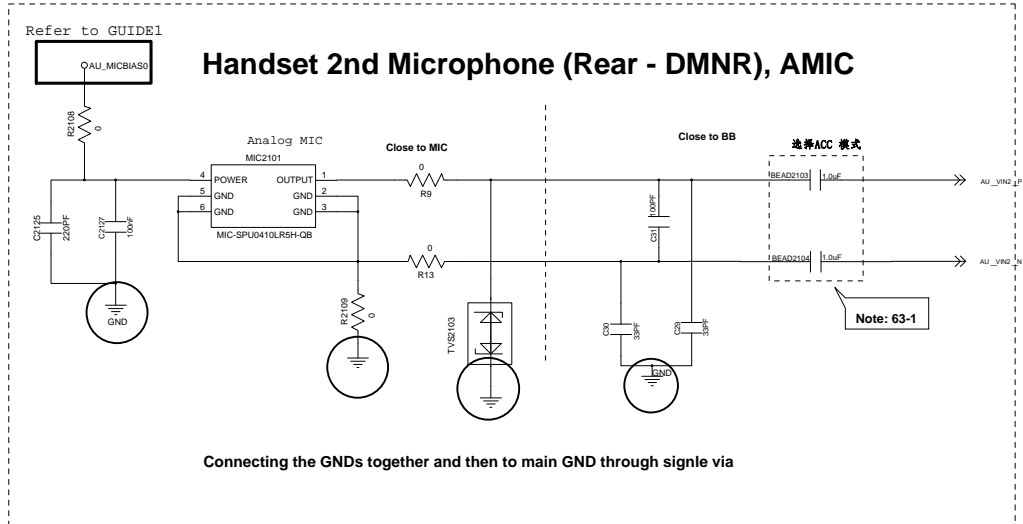
Note 62-2: Reserved Cap for CS/RS test, please double check multi-key function when used

Note 62-3:

	Earphone Jack # Main Board	Earphone Jack # Sub Board
R6212	0 ohm	100nF

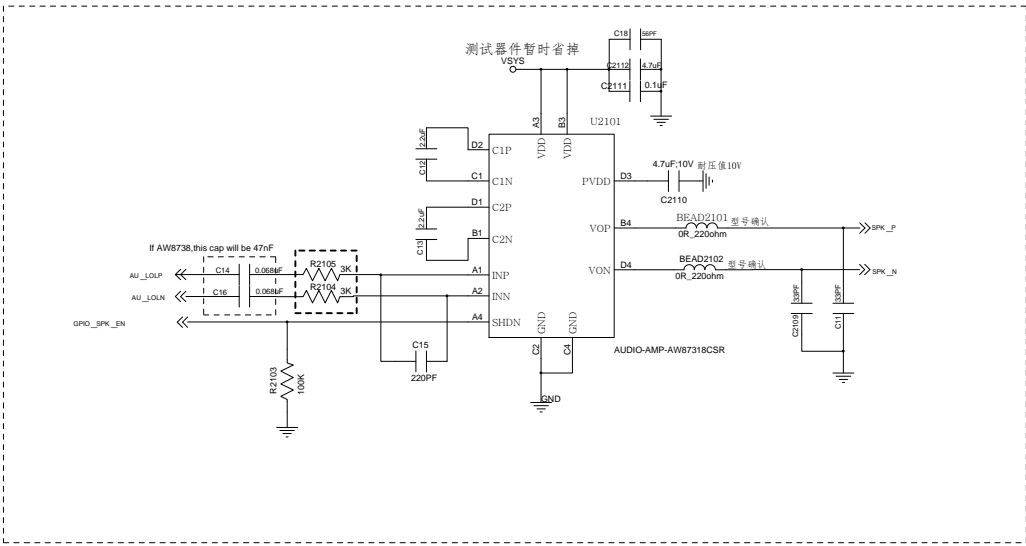
Note 62-4: Please Select ACC Mode for Operator Project to Pass Electrical MOS Test; More Information refer to Audio/Speech Design Notice

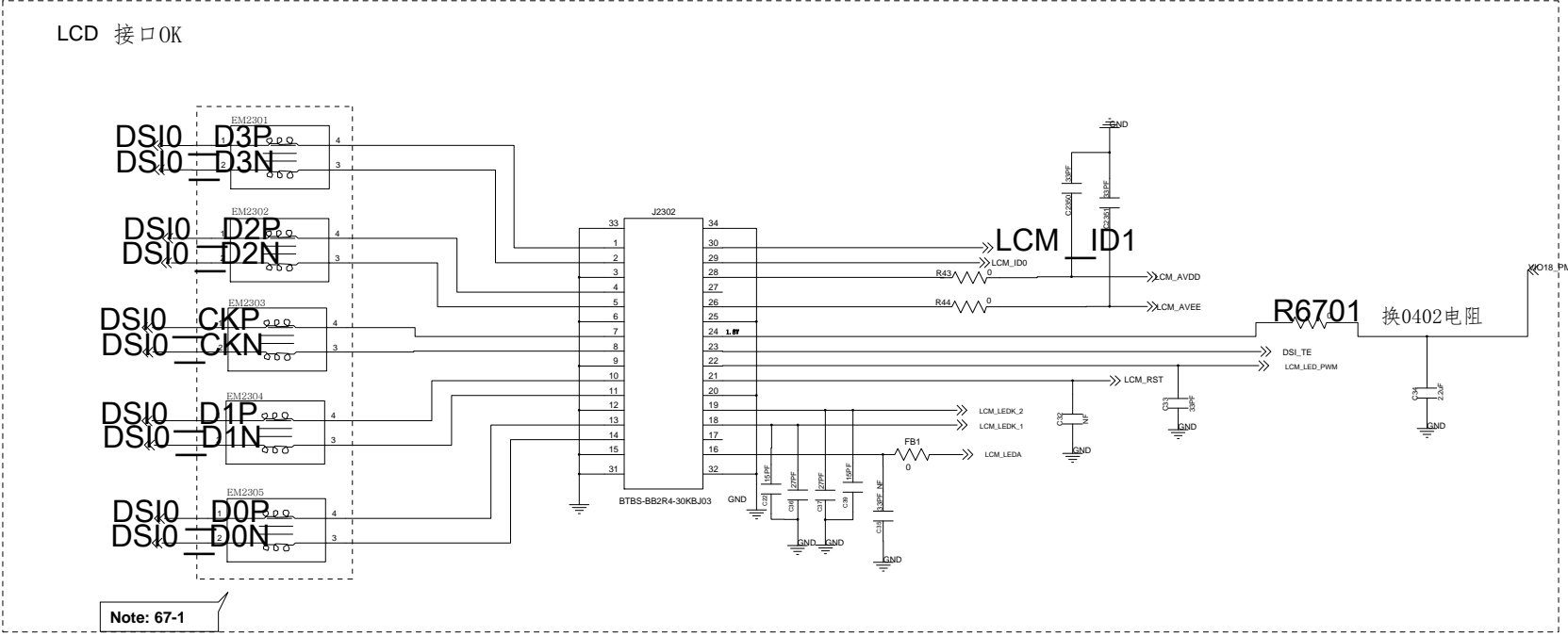
Note 62-5: Please select R6231 with 0402 size



Schematic design notice of "63_PERI_AUDIO_IO" page.

Note 63-1: 1 uF for ACC mode
0 ohm for DCC mode





Note: If best EMI practices are followed for MIPI CSI/DSI signals, there is no need for common mode choke filters. You may choose to have placeholders for common mode depending upon your design constraints. Extreme care must be taken that no stubs are created by doing so.

LCM ID
ID1 vender
EBBG

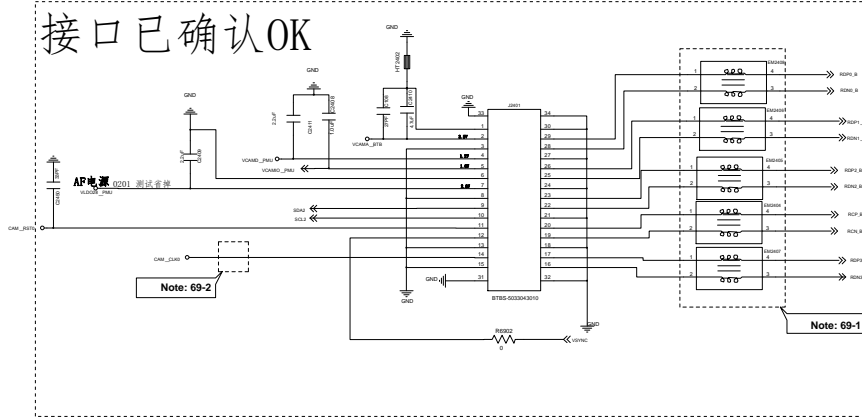
00		
0	0	5.5
1	0	5.5
0	0	5.5

Schematic design notice of "67_PERI_LCD_CTP" page.

Note 67-1: It is recommended to reserve common-mode choke to prevent RF de-sense, the max. cap loading of common-mode choke must be less than 3pF.

Main Camera

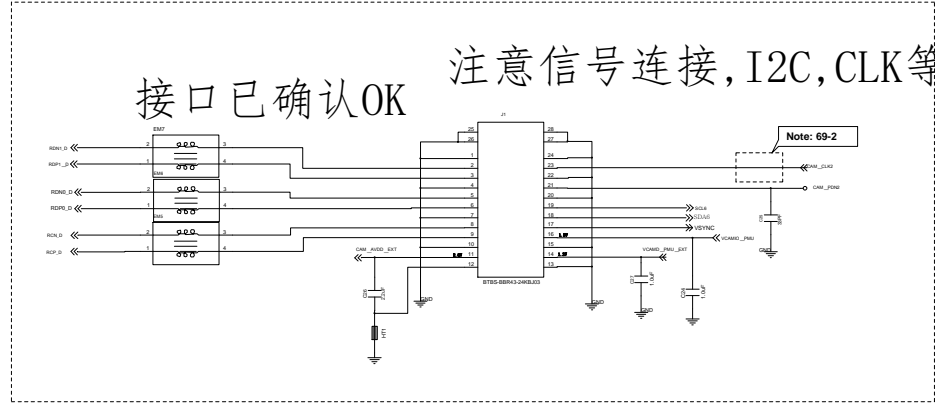
接口已确认OK



增加双摄

接口已确认OK

注意信号连接, I2C, CLK等的选用



Schematic design notice of "69_PERI_CAMERA" page.

Note 69-1:

It is recommended to reserve common-mode choke to prevent RF de-sense, the max. cap loading of common-mode choke must be less than 3pF.

Note 69-2:

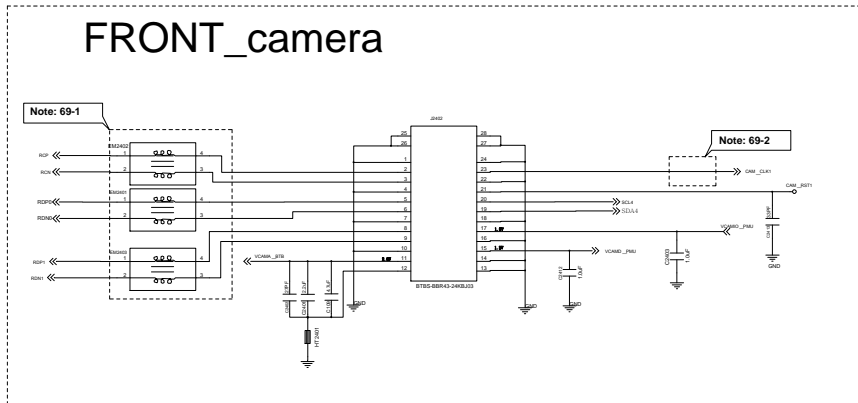
It is recommended to reserve 0-ohm for BOM fine tune to minimize RF de-sense.

测试器件暂时省掉

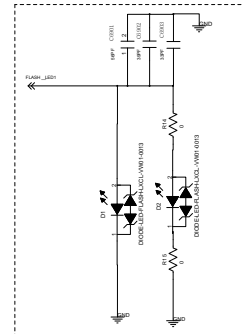


接口已确认OK

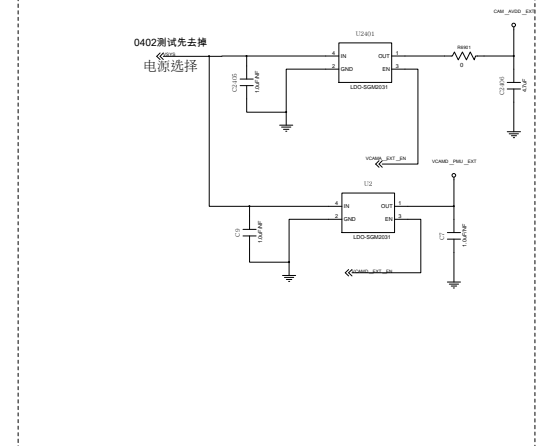
FRONT_camera



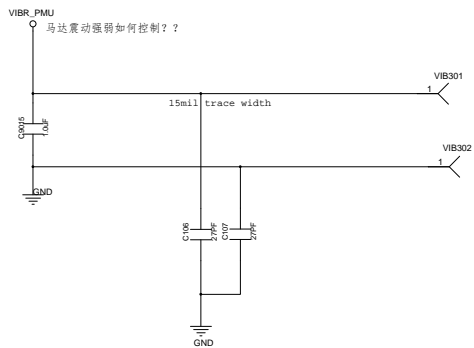
闪光灯



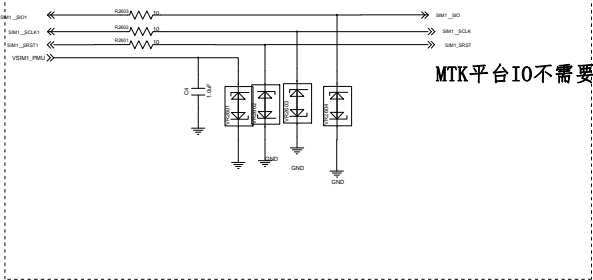
AVDD, DVDD需要单独增加LDO



VIBRATOR

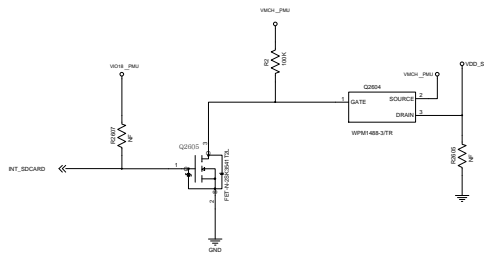


SIM1

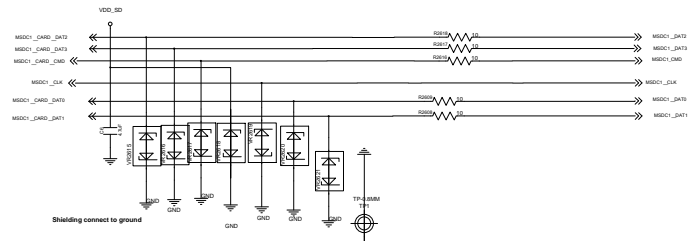


MTK平台IO不需要上拉

Vout=3.0V,I-lim=1A

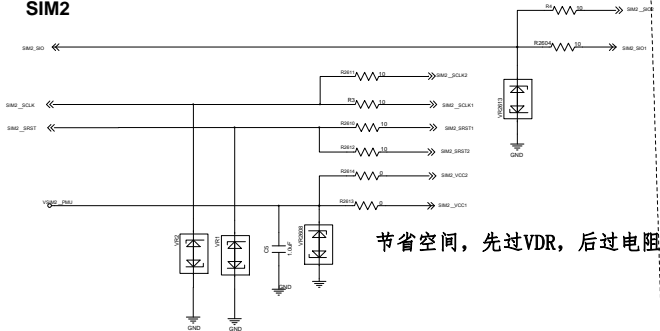


SD CARD

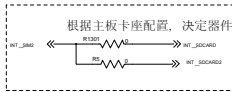


SIM2

MTK平台IO不需要上拉



节省空间, 先过VDR, 后过电阻

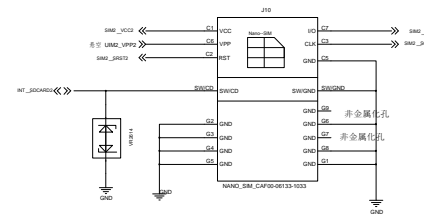


根据主板卡座配置, 决定器件

NOTE:

For internal version, ONLY use J2601:
R2603/R2610/R2613/R2604 can be 0Ω, R2611/R2612/R2614/R2615 can be NF,
R1301 can be 0Ω, Q2601 NF; R1302 NF

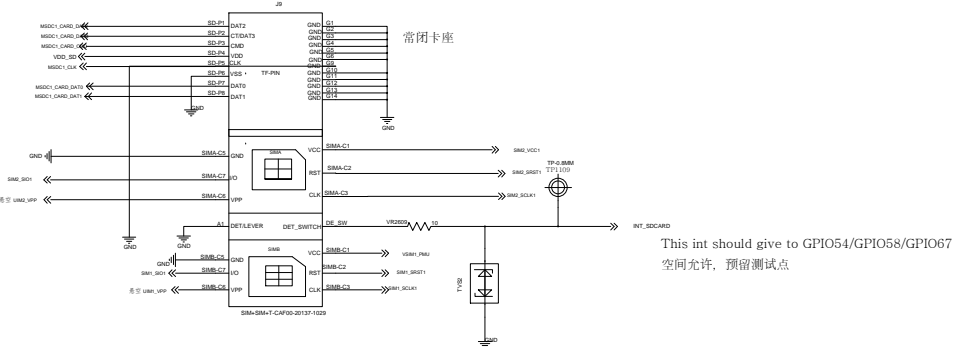
For India version:
R2611/R2612/R2614/R2615 can be 0Ω, R2603/R2610/R2613/R2604 can be NF,
Q2601 mount; R1301 NF; R1302 100K



常闭卡座

For internal version, R2603/R2610/R2613/R2604 can be 0Ω, R2611/R2612/R2614/R2615 can be NF,
For India version, R2611/R2612/R2614/R2615 can be 0Ω, R2603/R2610/R2613/R2604 can be NF.

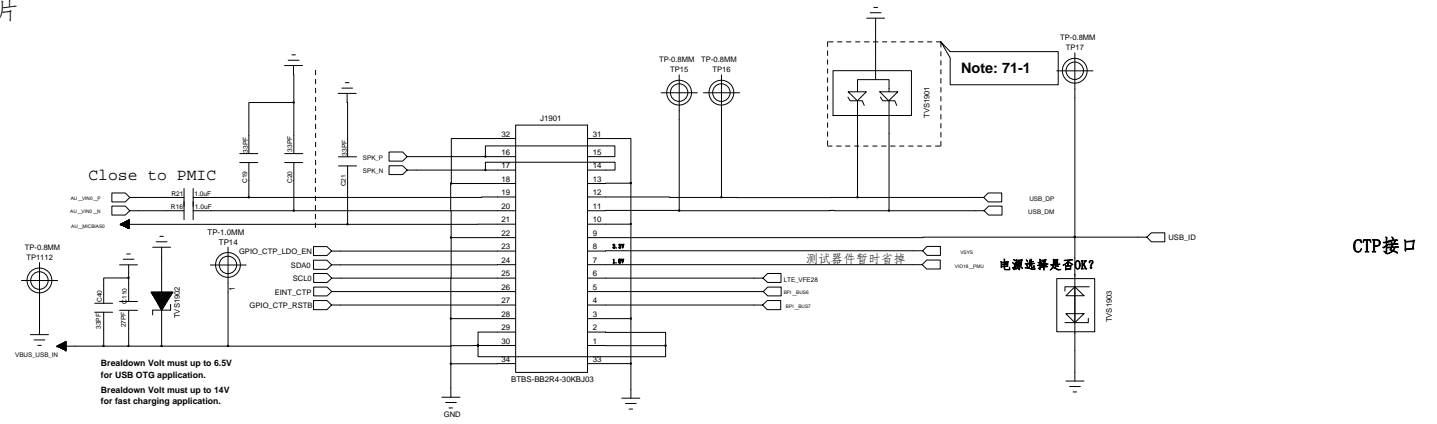
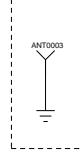
SIM/TF card



This int should give to GPIO54/GPIO58/GPIO67
空间允许, 预留测试点

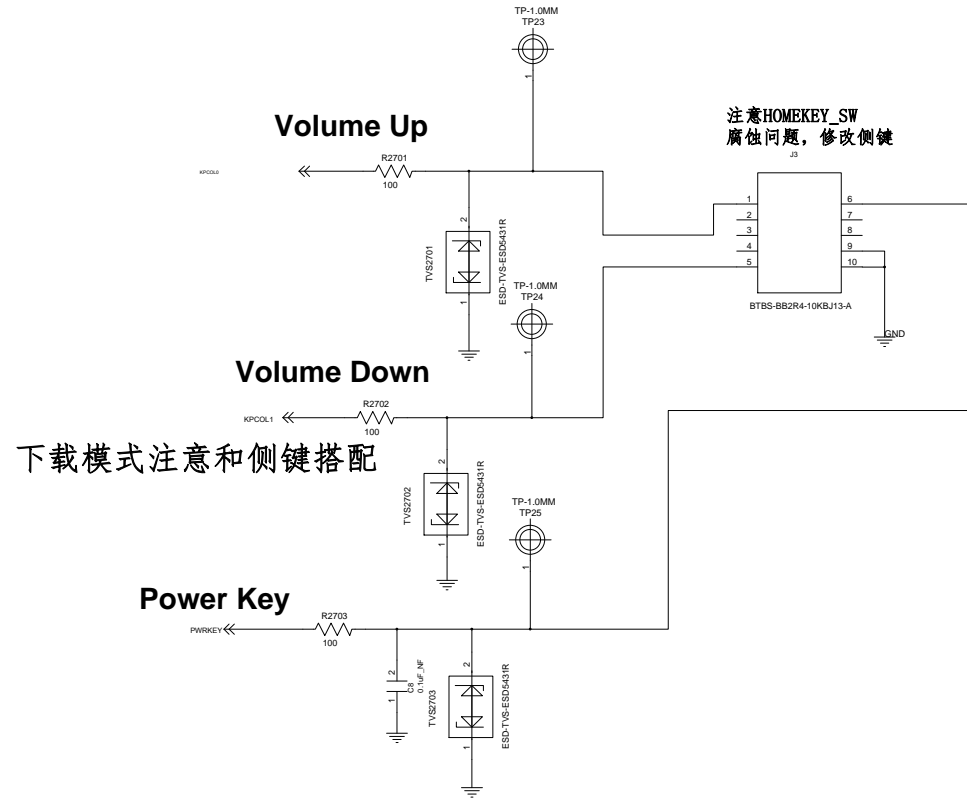
M-MIC+USB+RGB+SPK

主板接地弹片



Power Key / Key Pad

DO NOT put pull-up resistor on PWRKEY



RAMDUMP debug key 省掉??

下载模式注意和侧键搭配

Schematic design notice of "65_PERI_Dual_SIM_ICUSB_KEYPAD" page.

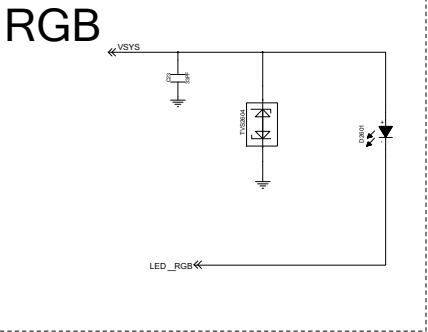
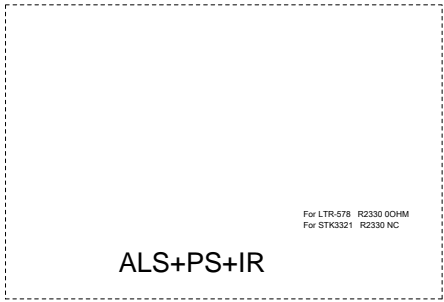
Note 75-1: DO NOT put pull-up resistor on PWRKEY

Note 75-2:

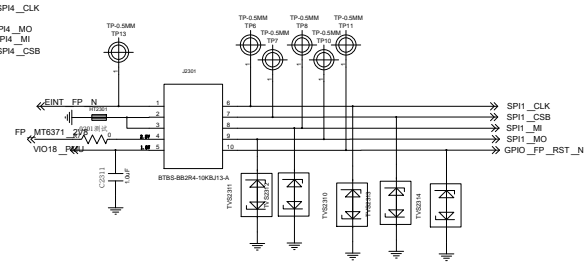
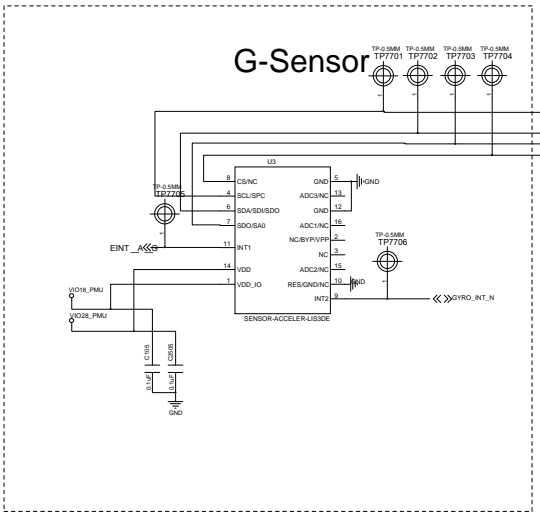
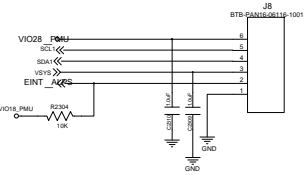
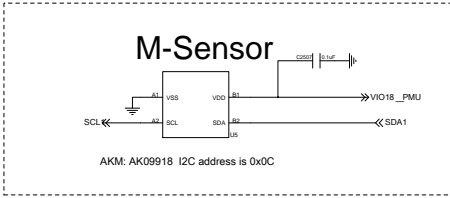
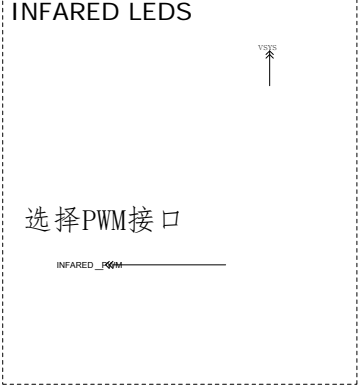
Volume Up : HOME Key / GND

Volume Down : KPROW0/KPCOL0

ALS+UV + Proximity Sensor
 CM36558 / ALPS + UV I2C address: 0X51 (Write:0xA2, Read:0xA3)
 CM36558 INT default Output High, Active Low



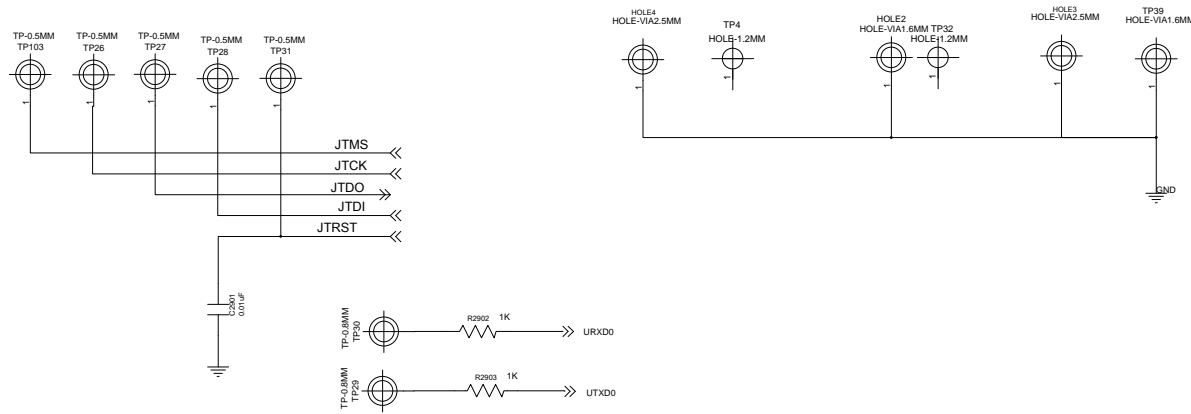
Accerometer + Gyro Sensor
 default SPI (if sensor hub support)
 6DSx INT1/2 default Output Low, Active high



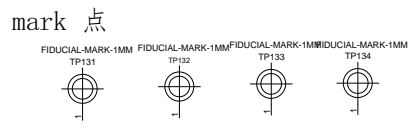
Replaced by fingerprint Sensor connector. follow 8996 placement

测试器件暂时省掉

- Schematic design notice of "77_PERI_SENSORS_MEMs_ALS/PS" page.**
- Note 77-1: [M sensor] Keep a minimum distance of 15mm from power ICs / PCB traces of more than 100mA / magnet component. Check HW design notice for more detail
 - Note 77-2: [A+G] For optimized GPS performance, please check HW design notice for Sensor selection guide
 - Note 77-3: [A+G] MUST use SPI for optimized sensor hub performance **DO NOT USE I2C**
 - Note 77-4: [A+G] Suggest choose sensor support FIFO watermark interrupt otherwise we cannot support Hifi-sensor, daydream VR. And Sensor-location accuracy will become worse.
 - Note 77-5: [Baro] Reserve Baro sensor for LPPe feature (Must for North America Operator / NA SKU)
 - Note 77-6: DO NOT share Sensor hub i2C to other non-SCP device



PCBA AUTOMATIC TEST point



Shielding Frame

	屏蔽盖	屏蔽框
BB	P1 屏蔽框 ↓ ICO-BOX	P2 屏蔽框 ↓ ICO-BOX
RF	P3 屏蔽框 ↓ ICO-BOX	P4 屏蔽框 ↓ ICO-BOX
SUB-PMU		P5 屏蔽框 ↓ ICO-BOX
WCN		P6 屏蔽框 ↓ ICO-BOX